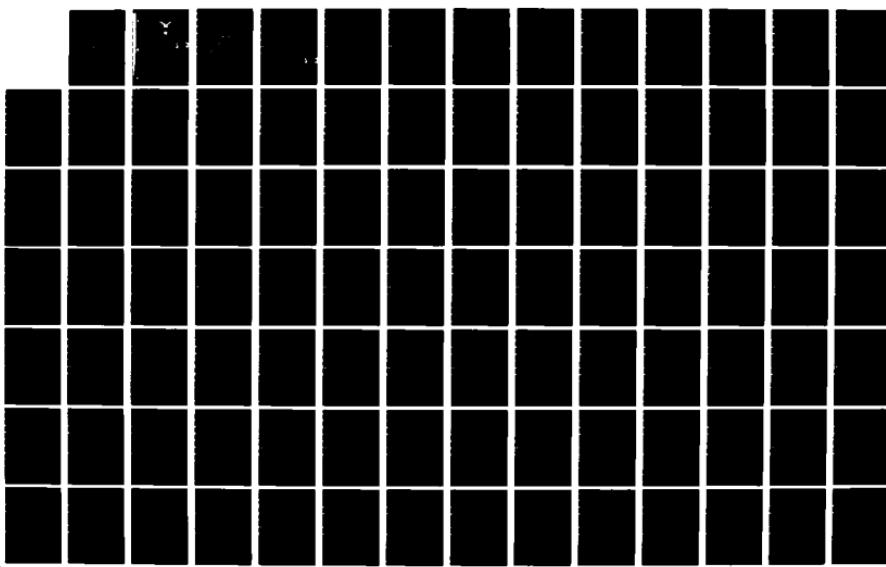
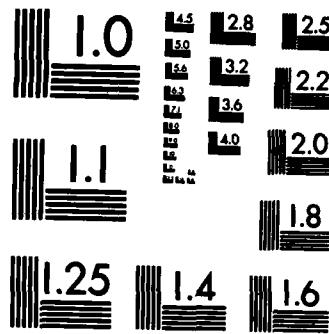


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CONTINUED DEVELOPMENT
OF THE
UNIVERSAL NETWORK INTERFACE DEVICE

THESIS

Presented to the Faculty of the School of Engineering
of the Air Force Institute of Technology
Air University
in Partial Fulfillment of the
Requirements for the Degree of
Master of Science

by

Cennaro Cuomo, B.S.

Capt USAF

Graduate Electrical Engineering

December 1982

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Preface

The purpose of this investigation was to continue the development of the Universal Network Interface Device (UNID). This involved the design and construction of a new memory board which incorporated two previously constructed memory boards. This investigation was limited to the development and testing of that new board and the UNID itself.

I would like to thank my thesis advisor, Dr. Gary Lamont, for his assistance and encouragement during the course of this investigation. I would also like to thank my readers for their valuable comments and aid in this study. The high quality support of the lab engineers and technicians saved me much valuable time and I would like to thank in particular, Capt. Lee Baker, Dan Zambon, and Orville Wright for their excellent support during the construction and testing phases of this study. Finally, I wish to acknowledge my gratitude to my wife, Linda, for her encouragement and understanding during this effort.

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Abstract

The objective of this investigation was to design and construct two memory boards for the Digital Engineering Laboratory Network's (DELNET's) Universal Network Interface Devices (UNIDs). The UNID is a flexible message processor designed for computer communications network applications. The new memory boards incorporated the prototype microcomputer based message processor memory boards of the previous theses. Using the existing memory boards, new memory boards were designed, constructed, tested, and documented. The results of this effort were the elimination of unreliable RAM, the reduction in the number of circuit boards used in the UNID, and two operational UNIDs.

(random access memory))

CONTINUED DEVELOPMENT
OF THE
UNIVERSAL NETWORK INTERFACE DEVICE

I. Introduction

The purpose of this investigation was to continue the development of an operational microcomputer based message processor with the inherent flexibility to permit its utilization in different types of data communications network applications. The need for a universal network device was first proposed by the Air Force Communication Service (AFSC) (28). There have been four previous investigations (22,5,1,17) into the development of a universal network interface device, and this investigation represents the fifth phase of the study effort towards an operating device.

The remaining sections of this chapter will address background information, followed by the scope, approach, and overview of the work covered in this thesis.

Background

Computer network theory and application, as developed over the past decade, enjoys widespread attention today. Computer networks have become an attractive alternative for increasing computational power and sharing computer resources. Undoubtedly the most successful example of computer networks is the current Defense Advanced Research Project Agencies Network (DARPA-NET). This packet switching network not only represents the future of computer communication, but also provides a valuable test bed for the development of new computer network technologies.

but also establishes network theory for later applications (14:5-23). One application of that theory is the CSNET (Computer Science Network). While the ARPANET is, or at least tries to be, a closed society limited to people who are working on Department of Defense contracts, CSNET is to provide network services to the entire U.S. computer science community (2).

Unfortunately, an international network of this size cannot be tailored to the needs of all potential network users. Using the ARPANET as a simple computer network interconnecting various minicomputers and microcomputers is impractical. These machines may not need the resources available through the ARPANET. A cost-effective and efficient computer network, dedicated to these smaller machines, would be more desirable. Such a computer network is commonly known as a local network (23:286-323).

Local networks tailored to a particular organization and interconnecting minicomputers became practical with the advent of the microprocessor. The microprocessor was the first development in support of local networks because it allowed economic network nodes to be developed. These nodes were cost-effective and yet offloaded much of the network protocol processing overhead from the computer hosts on the network. This made it practical for organizations to use a local network of microcomputers in lieu of time-sharing a mainframe computer.

A second fortunate development in support of local

networks was research into the design of routing algorithms and the techniques of flow control. Obviously, routing algorithms and flow control have direct impact on local network applications. An efficient routing algorithm insures that messages reach their destinations with a minimum delay (20:213-241). Likewise, sound flow control techniques will limit congestion on the network (20:242-258). Currently, these research efforts are yielding positive results for network applications.

A third important development for local networks came with an understanding of the need for network protocols. Protocols permit one machine to communicate with another machine through rules governing the timing and formatting of the data to be exchanged (13:35). Many different protocols and associated levels are now available with some movement toward standardization. The first protocols were developed as part of scientific research projects under ARPANETTM and the French Cyclades network (13:67-69). Commercial manufacturers have also developed various protocols. IBM developed the binary synchronous communication (BISYNC) protocol (23:120) and the System Network Architecture (SNA) (13:70), and DEC introduced DECnet (Digital Equipment Corporation network) (13:69-70). These are examples of machine dependent local networks.

However, within the last four years, more flexible local networks have become available. These networks are designed to interface many different types of machines. They are

examples are Ungermann-Bass's NET/ONE and Xerox's ETHERNET (15,3). NET/ONE uses a network interface unit (NIU) built around the Z80A microprocessor. The transmission medium is a baseband coaxial cable capable of transmission speeds up to 4 Mbps. The NIU is a significant feature of this network. A single NIU can connect to the network any one of a large number of dissimilar machines. Reconfiguration of the NIU for different machines is accomplished easily by loading different software. Additionally, each NIU is isolated from the network. Should one NIU fail, the rest of the network will not be affected. Further, NET/ONE NIUs contain most of the network protocols, making the network operation essentially transparent to both the user and the host (3).

The ETHERNET is similar to NET/ONE, but not as resourceful (15). ETHERNET does not use network interface units. This requires the subscriber to house the network overhead in his machine. Instead, a transceiver interfaces each user to the network. This transceiver isolates the network from user faults as well as connecting the user to the baseband cable.

A baseband cable uses a bidirectional signal path on which signals are encoded onto the cable. It only allows a single data channel and must be supplemented with other types of wiring to provide non-data-communications needs. Because the single data channel, baseband networks are slow, having data rates up to 10 Mbps over short distances (less than 100 feet). These distances can be extended to over 1 Km,

but reduced data rates from the effects of dispersion results. This is in contrast to a broadband cable which is a unidirectional signal path. Both a transmit path and a receive path must exist. This is accomplished either by splitting the available bandwidth into transmit and receive channels on the same cable or by providing separate cables for signal transmission and reception. Broadband supports multi-mode communications, including audio, video, and data on one cable pathway. Broadband networks have greater distance capability (from over 1000 feet up to several miles) while retaining full bandwidth because they use active amplifiers to distribute and extend the signal range. Broadband allows for greater distances than baseband but the data-rate decreases below 10 Mbps after several miles (12).

In many countries, the government or private industry began offering network services to any organization that wished to subscribe (23:28). These networks are called public networks similar to, and often part of, the public telephone and utilities systems. Such widely available networks needed common agreement on some form of protocol. With this approach many users operating dissimilar hardware could subscribe to this service. In an effort to provide standardized and compatible services throughout the world, these countries cooperate through the International Telecommunications and Telegraph Consultative Committee (CCITT) to develop "recommendations" for providing various types and levels of service (23:97). Several recommendations for various

switching network operations have been adopted in recent years, such as IBM's SNA, DEC's DECnet, Honeywell's Distributed Systems Environment (DSE), the United Kingdom's National Physics Laboratory (NPL) net and France's Cyclades net (4). Most notably is the X.25 recommendation specifying the interface or protocol to be voluntarily adopted by all manufacturers and users (13:71-73).

As local networks became more efficient and better understood, the U. S. Air Force began evaluating their potential usefulness. In the past, telecommunications requirements on an Air Force base were met in a single and straight forward manner by providing voice communications via telephone facilities, plus a few low-speed teletypewriter and data circuits over base cable systems (28:2). However, with the tendency toward use of digital processors to accomplish base-level functions, the base-level telecommunication facilities needed to be reevaluated to insure they could support the increased data communications needs (28:2). This reevaluation was accomplished in the 1842 EEG/EETC technical report TR 78-5 (28).

One facet of the TR 78-5 technical report involved the method of accomplishing the base-level message switching and distribution functions. At the base level, distribution of data and of other traffic is an important consideration since it encompasses user terminals and communication paths connecting them into the local area network. There are, in general, more user terminals

anything else in the network and thus costs associated with them are multiplied by a large factor.

To satisfy the base-level message and data switching, and distribution functions, the report postulated the need to connect any of the base digital processing devices to any terminal on the base and also the need to connect any base terminal to any other base terminal. To accomplish this interconnection, the "1842" report suggested three different types of network interconnections; the first was a star communication network with a centralized digital switch (28:162-163); the second was based upon the concepts used in the Advanced Research Project Agency (ARPA) network (28:164), and the last was the loop or ring network (28:164). The configuration the report finally recommended for the base-level data distribution network was a modification to the ring concept called a multi-ring network. This network consisted of a number of ring networks with a node providing interconnectivity between the rings. This multi-ring network concept offered particular advantages in terms of cost, development, application, and flexibility. A key to the multi-ring concept was the development of five types of devices which could interface the multiple rings together.

Rome Air Development Center was tasked with addressing the problem of the interface device. It was recognized that the various interface devices proposed had similar features and were required to perform similar functions. Thus, it appeared reasonable that one universal interface device

device (UNID) could be developed which could meet the separate requirements of each of the five proposed interface devices of the multi-ring concept. The subsequent development of the UNID and a local network application became the basis for numerous investigations. A preliminary design for the UNID was written in 1978 (22). The building of a prototype UNID based on this design was begun in 1979 (5). In 1980, the building of the prototype continued, modifications added, and the design refined (1). Also in 1980, the development and design of a local computer network for AFIT's Digital Engineering Laboratory Network (DELNETTM) was begun using the UNID and the loop network concepts (11). In 1981, concurrent investigations (9,17) continued development of the software for the DELNET, finished constructing the prototype UNID, built a second UNID, and implemented a prototype DELNET.

The two UNIDs were used as nodes, forming a simple local network following a previous design (11). The prototype network included two computers and several terminals using a fiberoptic communications link. The major components of each UNID were a card cage, motherboard, local processor card, network processor card, shared memory card, system memory card, local card, and network card (17:23).

At present, a concurrent investigation continues development of software for DELNETTM (10). Finally, investigation, completed in 1982, alleviates the concern which the previous thesis had with random access memory.

numerous quantity of dynamic RAM chips used in the system memory produced transient signals caused by the continual refresh. Circuit coupling and switching noise due to the wire wraps also created problems.

Scope

The basic hardware for the UNID is constrained by the design and implementation of previous investigators. This investigation remained within these constraints and continued the development of the UNID. The recommendations in previous theses were identified and implemented. These resulted in the design and implementation of a new memory board which combines the shared memory board with the system memory board.

This investigation elected to concentrate on hardware implementation and to write software only as necessary to test that implementation. A co-investigator (10) submitted most of the software support. Previously developed software was also used.

The development of the UNID suffered from the lack of current documentation. This investigation updated all cable connections, schematics, lists, etc., necessary for further development. This information is contained in the appendices.

Approach

First, an operable UNID was needed. At the beginning of this investigation no such UNID was available due to failures. Next, the memory boards were reevaluated to determine

static RAM chips, reducing the number of ICs and eliminating the circuit coupling and switching noise associated with the wire wraps. The reduction in ICs also eliminated the transient signals, caused by the continual refresh, which were seriously affecting the reliability of memory contents. Finally, both the system memory and shared memory boards were combined onto one memory board reducing 112 memory chips used to only 10 memory chips. Simple tests proved that the UNID's memory was now reliable.

Overview

This report covers hardware aspects of the UNID. Chapter II presents a summary of established requirements and design followed by a discussion of modifications implemented during this investigation. Chapter III details all construction modifications made to the UNID. Hardware testing of components is documented in Chapter IV. Chapter V summarizes the results of this investigation and recommends areas for further study. Finally, the Appendices contain all hardware documentation.

II. Requirements and Design

This chapter summarizes the requirements and design decisions established by previous theses (22,11,17). These requirements come from the initial design as discussed in Chapter I. These decisions formed the guidelines for this investigation. This chapter is divided into six sections: UNID requirements summary, DELNET requirements summary, DELNET design summary, UNID design summary, UNID implementation, and Documentation.

UNID Requirements Summary

In 1978, the 1842 E&G report was used to motivate the design of the UNID (22). The UNID, being universal, was based on the following general concepts (22:11-13):

- The UNID functions as a store-and-forward concentrator with message routing capability.
- The UNID includes specialized I/O ports to handle unique communication requirements.
- The UNID easily handles various network operating systems and communication protocols.

Using these concepts and structured analysis techniques (SAT), UNID functional requirements were developed (29,22:11-13). This approach developed an activity diagram consisting of a series of SAT diagrams showing system functions and their interrelations. Below is an outline summarizing these functional requirements:

I. Communication Interface.

- A. Flexibility.
- B. Signal Characteristics.
- C. Port Configuration.
- D. Protocol Software.

II. Local Information Processing.

- A. Receive local information.
- B. Store information.
- C. Process local information.
- D. Transmit information to network.

III. Network Information Processing.

- A. Receive information from network.
- B. Process information from network.
- C. Retransmit network information on network.
- D. Transmit information to local receiver.

- 1. Process control information.
- 2. Transmit information to subscriber.

Once these general functional requirements were stated, broad UNID bounds necessary for subsequent function allocation and design phases were established. Below is a list of these initial system bounds. Justification is presented in (22:34-46).

- Unid modularity based on circuit cards.
- Software implementation of different protocols.
- Synchronous, serial data rates up to 1.5 Mbps.
- Minimum of one full duplex network I/O port.
- RS-232C interfaces for local I/O ports.
- One local I/O port for 20 mA current loop.
- Interrupt controlled I/O ports.

The functional requirements allocation to UNID hardware and software was completed after establishing system bounds. At this point, three major components of the system were identified: local I/O, network I/O, and processing. Following this, subsuming the allocation to these components (22:48-49).

Local I/O Component (Hardware)

Recognize start of local information.
Recognize end of local information.
Recognize end of local message.
Transmit local information.

Network I/O Component (Hardware)

Recognize start of network information.
Recognize end of network information.
Change serial information to parallel.
Transmit network information.

Processor Component (Software)

Information to be transmitted.

Store outgoing local information.
Convert to network character set.
Identify ready to be processed information.
Process information to be transmitted.
Determine routing.
Initialize transmitter.
Identify information as sent.
Deallocate storage space.

Information received.

Store incoming network information.
Determine if error free.
Process information from network.
Identify as ready to be transmitted.
Identify type of message.
Remove protocol information.
Process control information.
Transmit information to 'local' subscriber.

Each entry corresponds to a particular diagram in the activity model (22:48-49).

DELNET Requirements Summary

With the requirements of the UNID complete, the next step was to design a UNID-based 'local' network for ARPA's Digital Equipment Computer Laboratory. This was done by first constructing a block diagram of the system.

(5,1,17). Two aspects of local networks motivated the investigation. First, local networks can increase processing power without adding more computers through resource sharing. Secondly, researchers and designers need a flexible local network testbed capable of supporting network theory development.

The DELNET design was a top down development using SAT. Design began by establishing user requirements for the development network in the Digital Engineering laboratory. A three-part user survey established these requirements. The following is a summary of the most important requirements for the DELNET (11:19-23):

- Ability to transfer files across the network.
- Ability to share peripherals attached to other hosts on the network.
- Flexibility in network configuration and operation.
- High percentage of availability.
- Performance monitoring capability.

These functional requirements were then used to establish DELNET system requirements, including both hardware and software. The system hardware requirements were essentially common sense approaches to network function, hosts, nodes, and transmission mediums (11:27-29). Topology must be flexible and easily expandable, free from bottlenecks that limit throughput and response time. New computers, regardless of their sophistication, should be easily added to the network. Computers with less powerful and/or popular peripherals should be avoided.

nodes should not degrade host performance, keeping the DELNET nearly transparent to the user. Nodes must reconfigure easily, accommodate different topologies and protocols, and meet network throughput. The transmission mediums must support data rates based on network throughput, response time, and bit error rate requirements. Finally, the DELNET should include a fiber optic link for research uses. System software requirements were more rigorously developed using several SAT's (11:29-30). Since this investigation is limited to UNID hardware components, the reader is referred to other investigations for a complete development of DELNET software (11,9,10). The software developed for this investigation was only that necessary to perform a component test.

DELNET Design Summary

Topology, hosts, nodes, and transmission mediums were specified in the DELNET hardware design (11). The topology selected is shown in Fig 2-1. The basic ring architecture is a simple version of the local network proposed in the TAC-EIG report (28). The star topology for the local side of the network was chosen for three reasons (11:85-86). This arrangement decreases the number of nodes required, making each node more cost effective. The topology provides a practical interface for both the simplest and most complex computers in the laboratory. Finally, the nodes can interact with each other through each computer attached to a single node, reducing the network complexity.

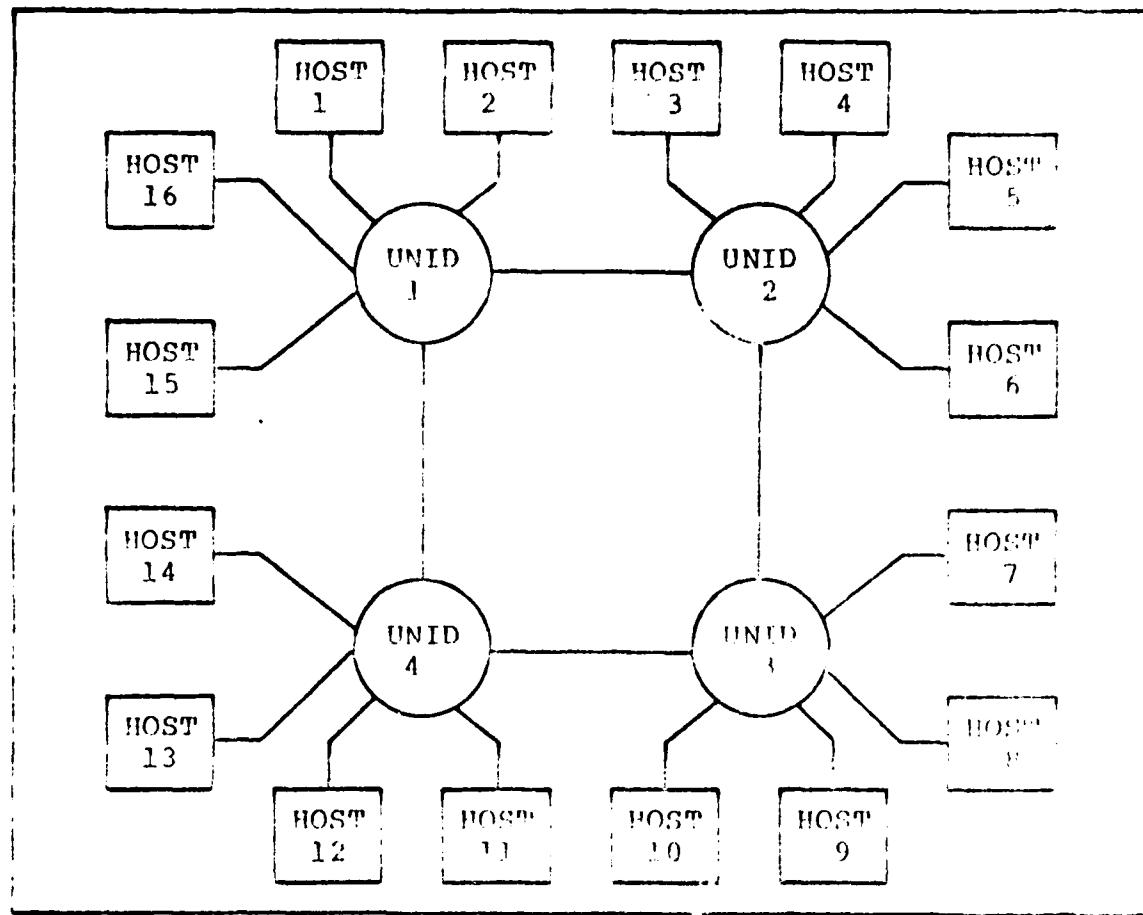


Fig. 2-1 DELNET Topology.

Three hosts for the initial implementation were specified (11:86-87). These machines represented a sufficient collection that would sufficiently exercise network protocol while providing the maximum resource sharing capability. The Vax-11/780 was chosen for its processing power, sophistication, and the capability to transfer files directly from the Cyber 750. The Intel series 38-MHz VME boards for its simplicity, high usage rate, and availability of management system. The third, the Data General 3200, was chosen for its high usage rate, its link to the Data General mainframe, and its compatibility with the other three.

The node specified for the DELNET is the UNID (11:87-88). Currently available commercial nodes and networks are too expensive and not flexible enough for DELNET requirements. The UNID, however, offered several advantages. Complete documentation on development and design is available and non-proprietary. The use of two Z80 processors permits parallel processing, minimizing throughput and response time delays. Finally, a high level language, PL/Z, and a software development system, MCZ 1/25, are in place and available for further development.

The transmission medium selected for the DELNET include both local and network channels (11:88-89). All local channels will use twisted pairs. One network link between two UNIDs will use a fiber optic communication channel.

Fig 2-2 shows the initial DELNET implementation with all the components discussed above.

UNID Design Summary

With the DELNET design complete, attention turned to the design of the UNID. The basic design of the device involved two Z80 microprocessor boards which share a 32K block of static RAM memory. Access to shared memory is through an arbitrator circuit (1:39) on the memory board. The UNID can interface to users directly and can interface with a communications network through local cards and network cards.

The Local card provides the means to interface up to four RS-232C users with the device. A GPO port is also serviced by a PINTU function. The architecture of the Local card

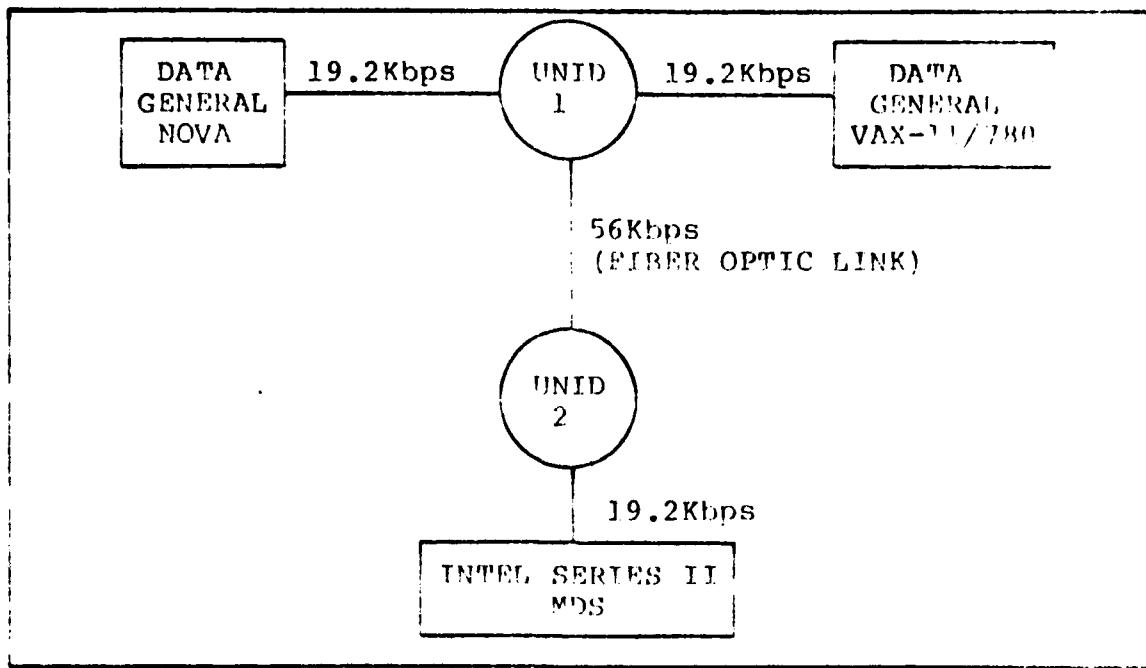


Fig 2-2 Proposed DELNET Configuration.

The network card was designed around the Z80-SIO, since the SIO provided significant capability for interfacing with different network protocols. Two network cards would be used in a device if the UNID was to act as an inter-ring interface mode. Fig 2-3 shows the block diagram of the UNID.

UNID Implementation.

Before a useable form of the DELNET could be built, at least two operational UNIDs were needed. These units, as shown in Fig 2-2, were used to form a least-cost minimum spanning tree (MST) network. In this case, the MST is a simple ring network dedicated to a private link between two nodes (20:171-174). In practice, more complex networks can be built by adding more UNID modules.

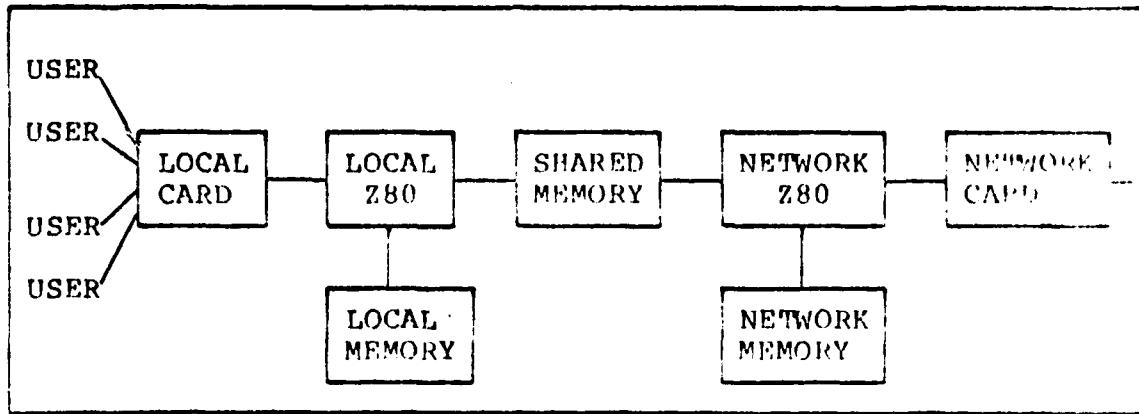


Fig 2-3 UNID Block Diagram.

shown in Fig 2-1. But, the MST approach requires a minimum of hardware to build a useable network.

A UNID prototype was completed by the end of 1980 (1). Since there was only one device, no numerical designation was assigned to it at that time. This device, however, did not meet the original design requirements. Specifically, UNID memory still needed to be expanded to 64K bytes and two additional I/O ports added. The next year saw these design requirements satisfied, a second UNID constructed (17), and numbers assigned. The first UNID built was designated number 1 and each of its cards were assigned the number 1, such as Local Card 1 and Network Processor 1. The second UNID completed was assigned the number 2, such as Network Card 2 and Local Processor 2. The two UNIDs are identical to each other except in numerical designation. Their respective boards are interchangeable although an attempt is made to keep each UNID's integrity. See Fig A-1, Motherboards, for what cards and I/O port assignments UNID requires.

a simple network was formed, a few problem areas had to be eliminated. The numerous quantity of dynamic RAM chips used in the system memory produced transient signals caused by the continual refresh. This problem was corrected by using static RAM chips. This also eliminated the associated circuit coupling and switching noise due to the wire wraps. The details of these improvements are presented in chapter III.

Documentation

This ongoing investigation relies on proper documentation to provide a clear understanding of past work and future needs. Thus, an important part of this report was complete documentation of current hardware. The documentation includes various schematics, test results, layout charts, and wire wrap lists. This information is found in the Appendices.

Summary

This chapter summarized the requirements and decisions for the UNID and DELNET. These represent the constraints placed on this investigation. These summaries were followed by the UNID and DELNET design implementation and evaluations conducted during this investigation.

III. UNID Implementation Modifications

This chapter details the implementation and modifications of the two UNIDs completed during this investigation. As mentioned earlier, there was no operable UNID available at the beginning of this thesis effort due to IC failures. The work accomplished to obtain such a UNID is discussed. Next, the design and construction of a system memory card is described. This led to the design and construction of two memory boards which consist of both system and shared memory. That work is described in this chapter.

Power Supply

Eventually, each UNID will be powered by a switching power supply, the Power/Mate ESM-200-4001, rated at 200 watts (18,17:27). One power supply was received; unfortunately, it had no power cables. An A/C power cord, connected through a switch, fuse, and indicator light was attached to the power supply. The four voltages (+5VDC, -5VDC, +12VDC, -12VDC) and ground were then connected to UNID 1. With the local ground grounded, each time the power supply was turned on, the signal would go to zero. It was determined that the power supply was switching intermittently. Therefore, it was returned and a replacement power supply ordered. In the meantime, the UNID was powered by a laboratory power supply. The Electronics' Model M60-10-0V power supply was used for this since, it was the only available supply with enough current.

capacity. The three-section Powertec Model 6C3000 power supply was used to supply the other three voltages.

The laboratory power supplies provided good regulation with essentially noise free power. An important feature of these two power supplies is their isolated DC grounds. The isolation prevents AC ripple and similar coupling interference reaching the UNID. All DC grounds were strapped together at the power supplies to further limit power supply interference. If different power supplies are substituted, care must be used to insure they are noise free and have isolated DC grounds. The replacement Power/Mate power supply was received; it was configured as the first and reconnected to a UNID.

UNID Update

At the start of this investigation, neither UNID was working on the local or the network side. Since each MCZ components are interchangeable (although numbered as previously mentioned), an operable UNID was obtained using UNID 2 Motherboard, MCZ Local Processor Card 1, Shared Memory Card 1 and Local Card 1. This UNID was only capable of filling and reading shared memory using a local monitor. It would not allow shared memory to be filled from the network to an improper bit pattern being transmitted to the MCZ when requesting a program transfer. The MCZ indicated that data bit 2 was a constant high. What this means is that during the transfer of program memory, the MCZ would wait for "data" and when receiving "data" it would ignore it. This is what

T.DEM07. This was due to a failed data driver chip on the shared memory cards. One driver chip on each of the shared memory cards had failed. Replacement of these chips gave the UNID two operable shared memory cards when a local monitor was used.

After the defective shared memory cards were fixed, MCB Local Processor Card 1, Shared Memory Card 1, and Local Card 1 were placed into UNID 1 cage. This configuration worked properly.

When attempting to operate the MCB Network Processor cards with a network monitor, the local processor card was not installed. This was due to the fact that both processor boards were supposed to be identical. In this configuration, with only a network processor and shared memory card installed, the UNID would not work. This was because the network processor had its system clock disconnected and was using the local processors' clock routed through an inverter on the shared memory board. After this was disconnected (shared memory card installed for network side to operate), the UNID had operable MCB Local and Network Processor cards, Shared Memory cards, and Local and Network cards.

Construction of the System Memory Card

System Memory Card 1 was constructed on a commercial Garry wire wrap card with certain modifications. Since each board contained enough space for three 28 pin sockets, each system memory board held three memory modules. An extension for each board was made and the card was

edge. The IC sockets for the network portion of memory were installed and glued into place.

System memory, built from static RAM ICs, requires +5VDC and DC ground (8). The component surface of each board is connected to ground and physically connected to pin 8 of each 16-pin socket. Where a 14-pin socket was used, pin 8 was wire wrapped to pin 7 to provide ground. The wirewrap surface is likewise connected to +5VDC and connected to pin 16 of each 16-pin socket. The system memory card contained all control logic and memory ICs necessary for operation.

Design of the Memory Cards

After building and testing the new system memory board it was discovered that when the boundaries between processor, system, and shared memories were crossed, such as writing memory from 1000(H) to FFFF(H), the system memory was unreliable. The reason was that the two separate buffers (system and shared) used two different address decoders to select the individual memory chips. For this reason, it was decided to design a new memory board which would replace both the system memory board and the shared memory board and use the new 8K X 8 static RAM chips. The new design incorporated the control and logic of the former boards.

Construction of the Memory Cards

Memory cards 1 and 2 were constructed using the same system memory card. All power requirements were the same. The only difference from the previous designs was the extension board. Instead of one end of the board

large enough to hold seven memory ICs. Memory cards 1 and 2 function identical and are completely interchangeable.

The memory board was wire wrapped after the initial design of the memory card was completed and a working schematic was available. The first wire wrapped board did not work properly, as will be explained in Chapter IV, Unit Testing. A second schematic was drawn based on board testing. Using this schematic (see Appendix B), a wire wrap program was generated and a second memory board was wire wrapped in accordance with this program. The program and wire list are shown in Appendix C. Based on the results of this second board testing and the wire list, the first memory board was disassembled and rewired.

The memory card contains all control logic and memory ICs necessary for operation. Appendix A shows the IC layout for the card. The top seven 28-pin chips are network system memory (2000(H) to 7FFF(H)) and shared memory (8000(H) to FFFF(H)). Below these are the three local system memory chips (2000(H) to 7FFF(H)). The rest of the chips on the board are for control.

Summary

This chapter provided a description of the construction of the UNITD memory cards. The chapter also defined supply requirements. In Chapter IV, the design and hardware difficulties will be discussed in conjunction with the UNITD testing.

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IV. UNID Testing

The final portion of this thesis investigation involved hardware testing the UNID and, in particular, the new memory cards. UNID testing was necessary in the beginning due to no operable system. UNID testing involved validation of wiring on the motherboards and all cards, functional logic tests, functional memory tests, and local card tests. The majority of the time was spent on testing the new memory cards. Hardware problems encountered are discussed along with their corrective actions. All testing was accomplished in accordance with previous theses (5,1,17).

UNID Testing Methods

The tests used to verify UNID operation were structured primarily as incremental bottom-up tests. This method was chosen for its several advantages in identifying errors. Once the initial components are checked, any new problems encountered are often caused by either an error in the newly added component or an error in the interaction with the new component. Also, the modularity of the UNID makes the incremental approach particularly attractive. Finally, none of the testing can be accomplished without existing involved hardware or software support.

The UNID circuit boards were tested as the incremental component. Several different were also tested in previous theses (5,1,17), but they limited its testing to validating correct values and

of card operation. At the outset of this investigation, there was no operable UNTD. With this in mind and needing a starting point, all cards were first given a power-off check. The next tests were power-on checks without ICs. This was followed by power-on checks with ICs added. As each card passed its checks another card was added. The following sections describe each major area of testing and discuss the results.

Power-off Testing

Each board used in the UNTD was checked for correct wiring. This check was accomplished when it was discovered that the UNTD was not operating at the beginning of the investigation. Although these point-to-point wire-trace checks did not detect any wiring errors, they did ensure that voltages were applied directly to ground and validated that signals were routed to the correct pins. This check also helped in learning what signals were on each board and how they operated.

Very simple methods were used to validate wiring. In some cases, the wiring was visually checked. In other cases, the wiring density was too great and a VOM had to be used to check continuity between pins.

Power-on Testing

The next series of tests were the power-on tests with no installed chips. A VOM was used to verify the correct voltage at the proper pins.

The ICs were then installed and the cards were rechecked.

UNID, adding one card at a time and checking it before the next card was added. Each card was checked for excessive heating when power was applied.

Functional Testing

Once the majority of wiring errors and faulty TUs were detected, each circuit card was tested to insure functional operation. The following sections describe this functional testing for each circuit card. The sequence of the following sections is the order in which the cards were tested.

Local Processor Card Testing

The local processor cards were functionally tested by installing them in the card cage, connecting the logic circuitry, and attaching an ATM-3 terminal as the local processor monitor terminal. These cards contained an 8080 monitor programmed during an earlier thesis (1). The local also contained 4K bytes of dynamic RAM. The functional testing involved resetting the processor card and executing the various commands in the monitor (1:12-16). Proper operation of these commands was considered sufficient evidence that the processor was operating correctly. More stringent testing, such as attempting to move and load data, was accomplished as cards were added to the UNID and the processor tasks became more complex. For example, using the LOAD command with the local card installed not only tested the on-card memory, but also initialized the memory, established the priority interrupt, set the data select, etc. Each of these functions, controlled by the local processor,

must perform correctly before a file can be loaded. Successfully loading data into memory was, therefore, taken as an indication that the local processor functioned properly.

Shared Memory Card Testing

The next cards tested were the shared memory cards. Each local monitor processor command was reinitiated, this time executing the commands within the boundaries of the memory on the shared memory cards. The shared memory was filled entirely with 00(H); then, the entire memory was displayed. This fill-display routine was repeated using different hexadecimal characters until all memory data bytes were switched from zero to one to zero. Each time data was to be a zero, a one was displayed. This indicated a problem to the data driver chips on the shared memory board. A chip driving the network side of shared memory had failed when it was holding that bit high in memory. A similar problem was encountered with both shared memory boards and the boards were similarly. After replacing the chips, a block of data was moved several times from one location to another within shared memory, then displayed. Finally, a single block (one location) of data within shared memory was addressed repeatedly. These three procedures were taken to test the basic operation and characteristics of the shared memory.

Network Processor Card Testing

After the Local Processor and shared memory were tested for proper operation, the Network Processor card

installed. As stated previously, this board was tested similarly to the local processor card. The only difference between the two cards is that the network processor card has no clock and needs the local processor card installed. A previous thesis discovered the local and network processor cards would operate together without interfering if the network clock was disabled, using instead the inverted clock from the local processor card (5:64-65). This inversion was obtained by wiring the clock signal from the local processor card through an inverter on the shared memory card and back to the clock circuit on the network processor card. With the proper boards installed, the terminal monitor described in the Local Processor Card Testing section was repeated for the network processor card. Similar fill-display routines in the Shared Memory Card Testing section were performed on the network processor card. Finally, the three cards were tested together. The sequence of filling a portion of the local processor's on-card memory, moving that block into shared memory and then moving that same block into the network processor's on-card memory, was run the network processor monitor. The entire test was then reversed, starting with the network processor's on-card memory and ending with the local processor's on-card memory. The sequence was repeated in the reverse direction for different memory locations.

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Local Card Testing

The local card was added to the UNTD when the above series of tests were completed. A data file on disk in the MCZ was attempted to be loaded into the UNTD through port Channel 1 using the load command. The file was unable to load due to the shared memory card's IC failures as related in Chapter III, UNTD Update. After correcting the problem, the file's contents and location were validated visually.

System Memory Card Testing

The testing of this board was accomplished as outlined in the beginning of this chapter. The problem of unrelatable data due to boundary crossing has been discussed in Chapter III. This led to the design of a combined memory board.

Memory Card Testing

The memory card would not operate properly when tested after construction. Basically, three different types of problems were found on this card: faulty design, faulty parts, and timing faults. Each type of problem and its solution will be discussed in the following sections.

Design Faults

The memory card was originally designed to connect to common address lines common to shared memory, local memory, and network system memory. An address line was selected by a previous bus control logic to identify the connection between the local and network memory and the shared memory. This connection was to be used with the local memory to the network memory.

XSEL and a YSEL depending on which processor MRQD signal arrived first. The present investigation NORed XA13, YA14, and XA15 together and NORed YA13, YA14, and YA15 together (see Fig. B-2). This was accomplished to create an YSEL or YSEL, whenever a memory location of 2000(H) and above was selected either on the local side or the network side. The XSEL and YSEL signals are used to enable the address bus multiplexers. The XMREQ and YMREQ were used to select the data line bi-directional bus drivers.

The local system memory portion of the memory board was completed first and tested in accordance with previously discussed testing methods. This portion of the board passed all tests. The next portion of the board to be completed was shared memory. When this portion was tested, it was discovered that both the local system and shared memory bus drivers were being enabled at the same time when trying to read local system memory. This was causing a conflict on the data lines. To alleviate this problem, first, the data lines were separated so that each section (local, network, and shared) had its own dedicated lines. Then YMREQ and XMREQ were each NANGED with YM80 and XM80, respectively, so that the network and local shared data bus drivers were selected if shared memory was not addressed. This caused the local system and shared memory portions to work in parallel. After the network portion was completed, it was determined that both the network and local system memory could be connected together by the shared memory bus driver.

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because the same chip select line (CE-XY2000, CE-XY4000 and CE-XY6000) was being used to enable each data bus driver. The only difference between the two was that each had its own read and write signals (XRD, XWR, YRD, YWR) for DTEN (Data In Enable Direction control). To correct this problem, the three chip select lines were NANDed together to create one chip select signal, CE-XY, which was then NANDed with either XSEL or YSEL, depending on which portion of the board was addressed. Now the individual portions of the memory were worked correctly.

Integrated Circuit Faults

An IC fault occurs if a chip fails to perform according to its truth table or specified function. Typically, a high fault, where the output remains high under all conditions, is corrected easily. The chip is simply removed and replaced. A fault where the output remains low under all conditions is more difficult to identify. A low condition fault can be caused by an internal short, an external short, or an internal short in the next stage. One effective way to determine an IC fault involves removing and replacing chips. A suspected faulty IC is removed and replaced by a known good IC. If the circuit then works correctly, the suspect IC was probably the cause of the fault. If the circuit still works incorrectly, then the suspect IC is returned to its place and another chip is placed in its place. This process is continued until the faulty IC is removed and replaced. In this case, the faulty IC was found to be the NE555 integrated circuit.

wiring.

After redesigning the data bus drivers of the system memories, it was discovered that when the local monitor was used to fill shared memory with 00(H) and read, it displayed 00(H); but, when the network monitor was used to fill shared memory with 00(H) and read, it displayed 40(H). Data line DQ6 (pin 18) of the shared memory chips was only high when filled by the network monitor. When the network shared memory data bus drivers were removed, the shared memory worked fine. These two chips were then reversed and returned to their sockets. The result, when again filling with 00(H), was a displayed 04(H). The original data bus driver for line DQ6 was replaced with a good chip and the circuit functioned correctly.

While testing the new memory board, the local processor card failed. The only indication was that the local monitor would not reset. After checking the address lines and their associated chips, the data lines and their associated chips, and the EPROMs, it was discovered that one of the EPROMs had failed. This discovery was made by replacement with known good chips. The problem was not eliminated. A logic analyzer, in the memory map mode, attached to the CPU's address lines showed that the monitor program in the EPROMs was randomly addressing all of memory instead of remain in a tight loop waiting for an interrupt. This indication led to the stack pointer. The memory location of the stack point is resident in RAM, so the memory chips were replaced one by one

to determine if they were causing the problem. These were the only chips on the board which had not been examined. One chip had failed. It was removed and replaced with a good memory chip and the processor board then worked properly.

Memory Timing Faults

After the above faults were detected and corrected, the new memory card still failed to operate properly. The network system memory and the shared memory each worked correctly, but, the local system memory did not. During fill and display memory operations, a set pattern of unchanged data always occurred. The local and network sides were designed and wired similarly, but the local side would not create a chip select to any of its memory chips. All wiring and chips were checked and found to be proper. A chip select was forced by routing the CE-XY2000 signal to local memory chip G1. This allowed the chip to operate but resulted in the same design problem as before (local and network memory being selected at the same time). The forcing of a chip select signal to G1 by-passed the ORing of CE-XY2000 and XSEL. This indicated a timing problem. These two signals were routed not from their sources but from other pins of the same signals. To ease the timing problem, the two signals were routed to the OR gate from their respective sources. This helped, but some unreliability in memory remained. A faster OR gate chip (74S32) was then used and the circuit worked perfectly.

UNID Testing

Once the memory card was found to be working by performing the simple monitor commands, a test program (L.VINT) was loaded into local system memory from the MCZ and run successfully. Then, the same program was moved into network system memory and run successfully. When this program was attempted to run in both local and network system memories simultaneously, only one side would run. Whichever memory (local or network) was started first would run until the other was started and then the first would stop. Not only would it stop, but the contents of its memory locations would be changed. Also, while running this program on the network side, the local side was loaded again from the MCZ. Loading caused noise interference to occur on the network monitor, and when the network side was then stopped and attempted to be restarted, it would not run.

At this point all checks were again run on the memory card and no errors were detected. This board was wire wrapped in accordance with the original design schematic. According to that diagram and the wiring of the board, the local and network sides were completely independent and showed no reason for interference. From the schematic a wire list program was completed which gave the signals at each pin and the routing of all wires. The board was then compared to the wire list and no discrepancies were detected. Since there seemed to be no differences between the board, the schematic, and the wire listing, and no faulty ICs could be

detected, it was decided to go ahead and construct a second memory card in accordance with only the wire list program. When this second board was completed and tested it also had a timing problem as mentioned earlier. The problem was corrected with the previously stated modification to the wire list (see Appendix C). The same program was then loaded into both sides of this board and attempted to run simultaneously. No interference was discovered and both sides ran independently. The first memory board constructed was then rewrapped in accordance with the wire list. Then, it was tested, as previously stated, and found to operate properly.

Chapter Summary

This chapter describes the testing performed on the UNID. The testing scheme chosen was organized from the bottom-up and followed the procedures of previous theses (1,5,17). The type of tests used were power-off, power-on, and functional tests. Also discussed were types of circuit problems encountered and solutions to the same.

V. Summary and Recommendations

The objective of this investigation was the continuation of the development of two message processors (UNIDs). This involved the designing, constructing, and testing of a new memory card. The software used in this thesis investigation either existed or was developed by a co-investigator (10). This chapter summarizes the results of this effort and suggests areas for further study.

Unit Completion

When this investigation began, two UNIDs were complete but neither was working. During this investigation, the two prototypes were tested for faulty wiring and ICs. All discrepancies found were corrected to produce two operable UNIDs. Completing the UNIDs required that a new memory card be constructed incorporating the circuitry of local and network system memories, and shared memory. The memory card was built using new technology, 8K X 8, static RAM chips. These memory chips allowed all 80K of memory to be built using only 10 memory chips and 33 control and logic chips.

UNID Testing

Each UNID was tested using an incremental bottom-up routine. Most of the UNID testing was limited to detecting IC faults inherited from previous theses. The remainder of the time was spent on testing the new memory card. Functional testing of this card revealed serious design

errors. These errors were finally corrected and two operable UNIDs are now in effect.

Recommendations

These recommendations include suggestions from past theses and involve further hardware development for the UNID and DELNET. Implementation of the Z80A processor is still a requirement of the original design. This involves replacing each Z80 MCB with the faster Z80A board. Unfortunately, Zilog no longer produces a Z80A MCB board. So, to upgrade the UNID a processor board would have to be designed and wire wrapped incorporating the Z80A CPU and associated circuitry. If a new processor board was designed and constructed it would be able to use the new static RAM chips and eliminate the dynamic RAMs now used on the MCB boards.

Also for future investigation is the use of a new Zilog 8-bit micro-processor chip which should be available in 1984 (25). This Z8108 has a multiplexed address and data bus to reduce the package pin count without sacrificing performance (memory transactions still require only three clock cycles). In addition, design with the Z8108 would be easy because of the on-chip oscillator and programmable bus timing features. The only external element required in the oscillator circuit is a crystal (whose frequency is twice the desired internal frequency). This chip can operate at speeds of 6 to 25 MHz for increased throughput. The programmable bus timing feature increases system throughput. Control-bit settings allow the internal processor clock to be scaled for external

bus accesses and wait states to be automatically inserted during bus cycles. Consequently, the user can select very high clock speeds to increase system performance without requiring high-speed memories and I/O devices.

Another recommendation deals with the network card. The original design goal for the network data rate is 1.5 Mbps. The Z80A-SIO can function at 880 Kbps in half duplex mode. The desired rate could be reached using the Signetic's 2652 Multi-protocol Communication Controller (MPCC) (20). The MPCC data rate is 2 Mbps and contains all Z80A-SIO features. It can also interface with an 8-bit or 16-bit data bus. Thus, this addition would be compatible with 16-bit message processors.

Now that there are two operable UNIDs having reliable static memories, future investigations will be able to concentrate more on the development of the DELNET rather than the hardware of the UNID.

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APPENDIX A

CIRCUIT CARD LAYOUTS

This appendix contains a collection of diagrams illustrating the IC layout for three circuit cards used in the UNID, including the motherboard. The local and network processor cards are not included here, but are well documented in the Z80 MCB User's Manual (27).

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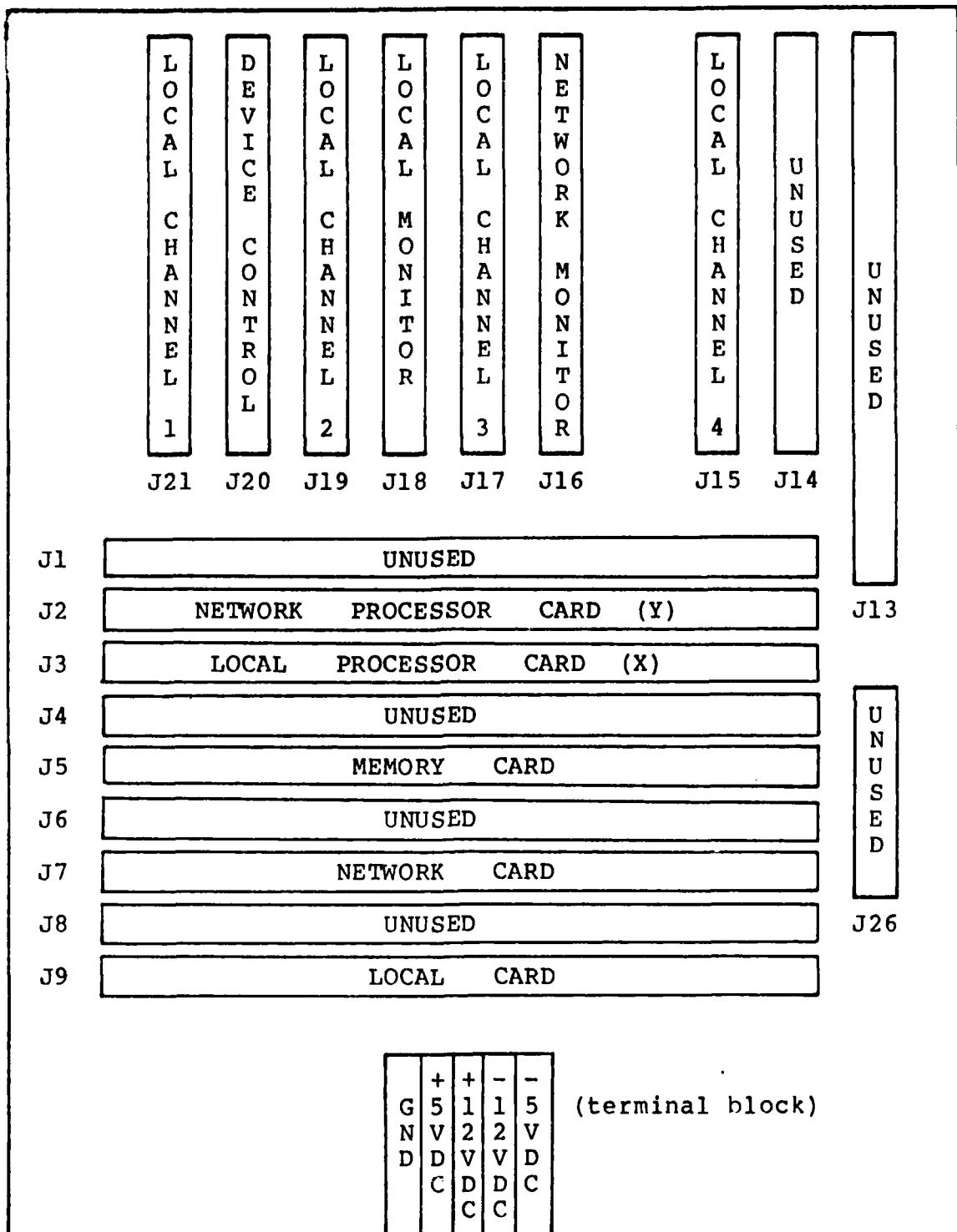


Fig A-1 Motherboard Layout.

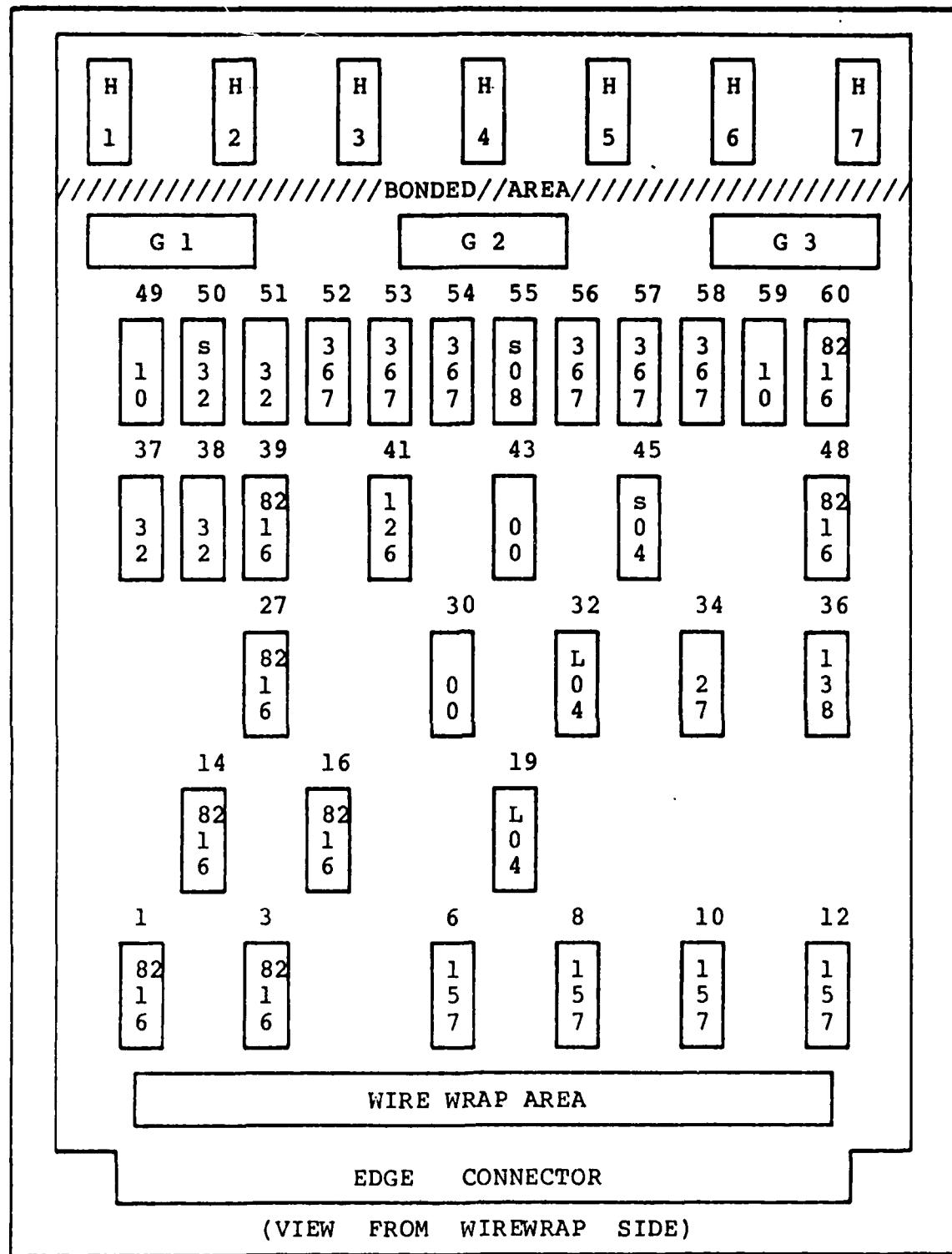


Fig A-2 Memory Card Layout.

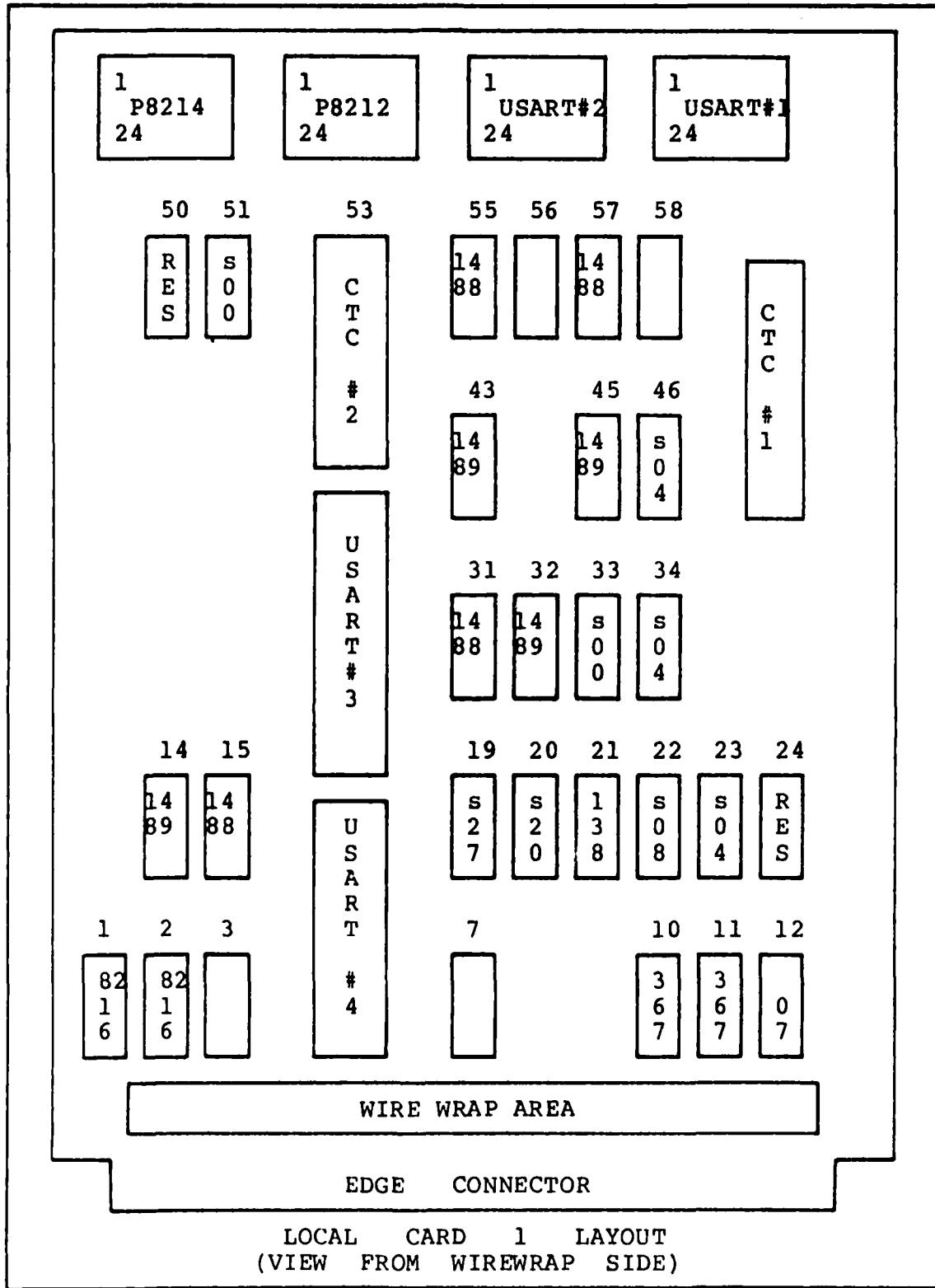


Fig A-3 Local Card 1 Layout.

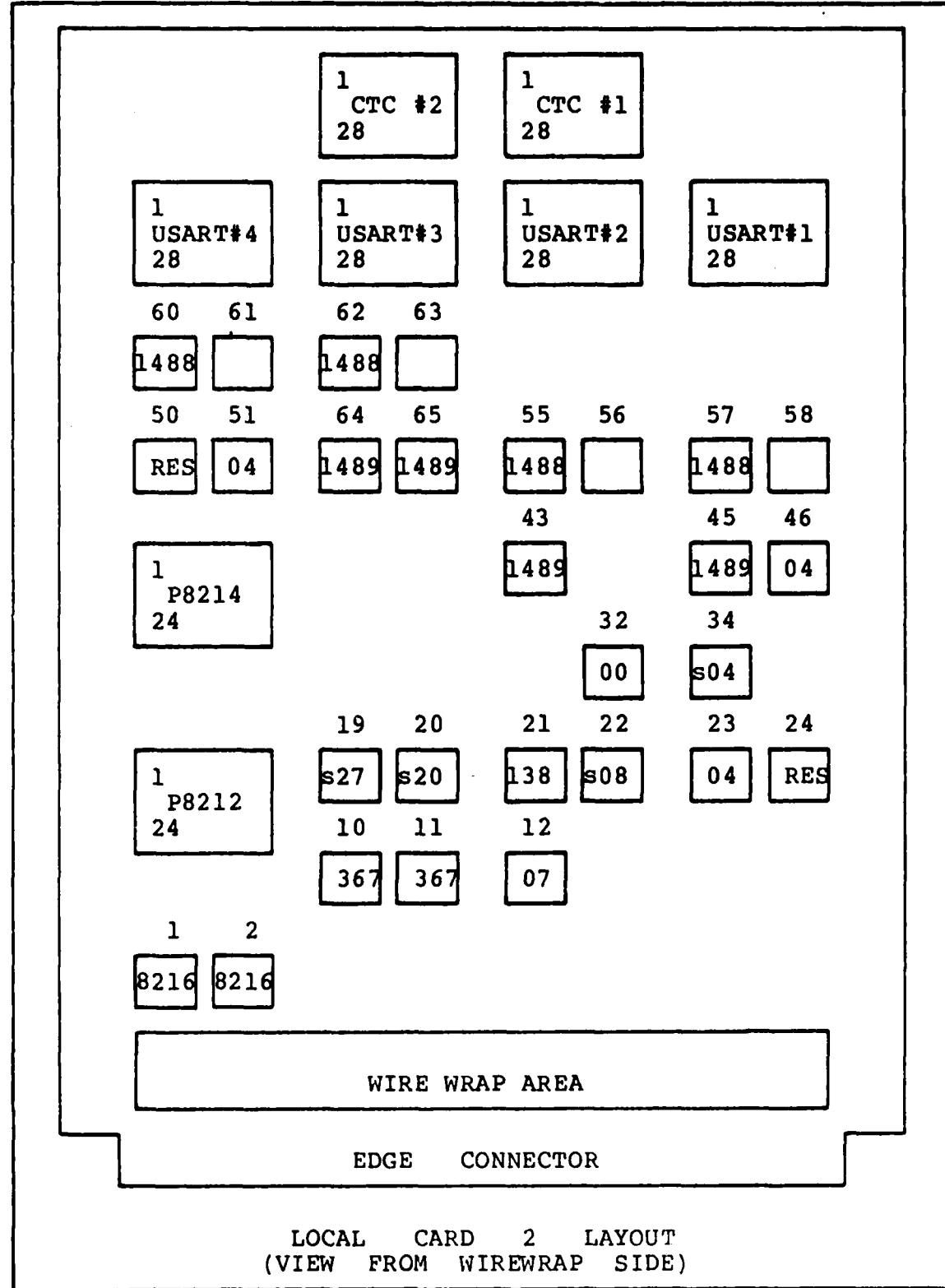


Fig A-4 Local Card 2 Layout.

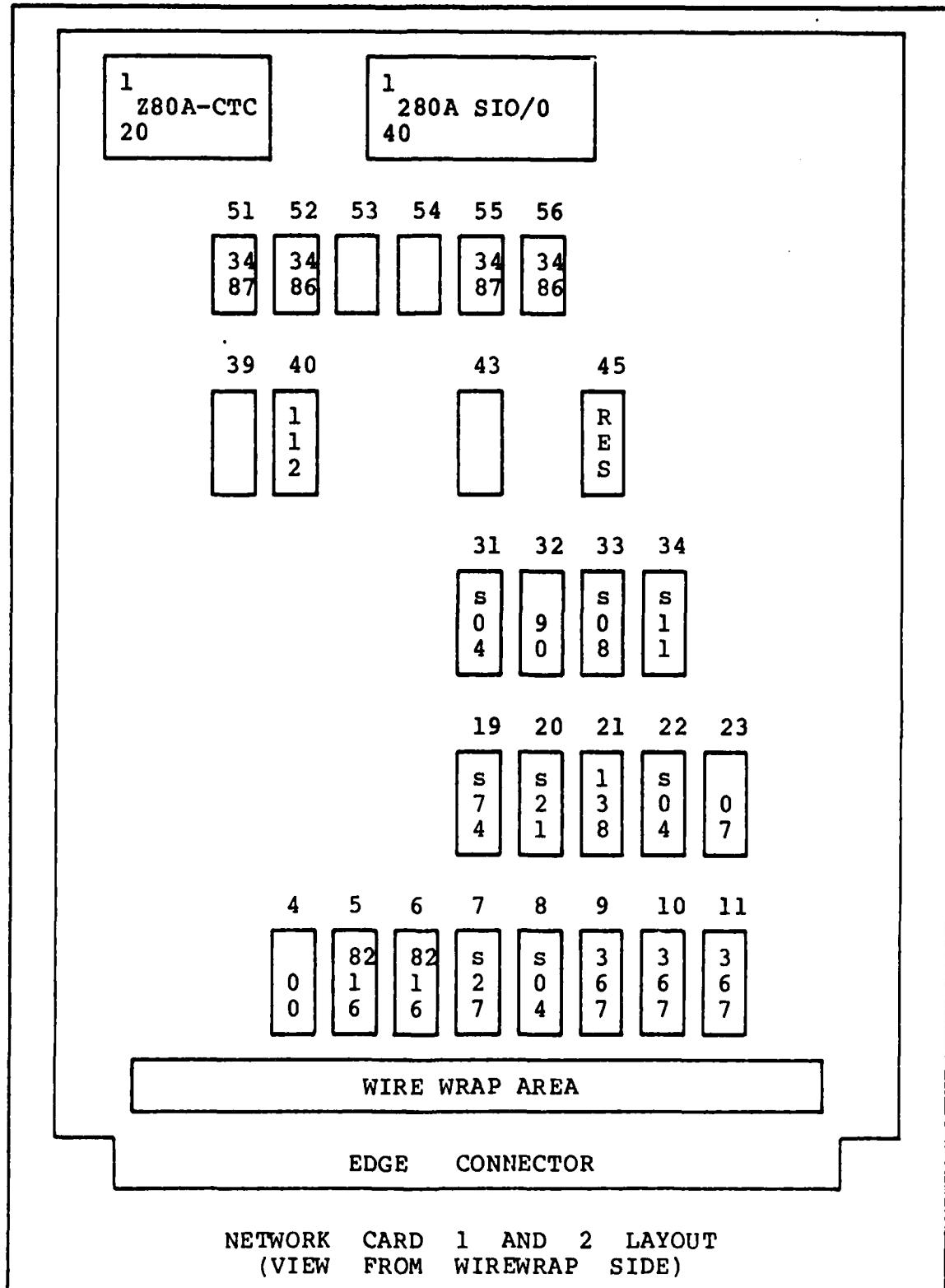


Fig A-5 Network Card Layout.

Appendix B

Circuit Card Schematics

This appendix contains the circuit schematics for three of the UNID circuit cards, including the motherboard. The circuit schematics for the local processor and network processor cards are contained in the Z80 MCB User's Manual (27).

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This figure lists the wiring connections made on the motherboard of UNIDs 1 and 2. The head of each column corresponds to a connector on the motherboard. The vertical column at the left of the figure lists the particular signals being described. The numbers in the figure represent the wire wrap pin numbers where the signal is attached to the given connector. All signals on the motherboard are grouped according to function.

	<u>J2</u>	<u>J3</u>	<u>J5</u>	<u>J7</u>	<u>J9</u>	<u>J15</u>	<u>J16</u>	<u>J17</u>	<u>J18</u>	<u>J19</u>	<u>J20</u>	<u>J21</u>
LOCAL PROCESSOR ADDRESS BUS (X)												
XA0	*	103	90	*	103	*	*	*	*	*	*	*
XA1	*	102	92	*	102	*	*	*	*	*	*	*
XA2	*	101	94	*	101	*	*	*	*	*	*	*
XA3	*	100	96	*	100	*	*	*	*	*	*	*
XA4	*	98	91	*	98	*	*	*	*	*	*	*
XA5	*	29	93	*	29	*	*	*	*	*	*	*
XA6	*	30	95	*	30	*	*	*	*	*	*	*
XA7	*	26	97	*	26	*	*	*	*	*	*	*
XA8	*	27	29	*	27	*	*	*	*	*	*	*
XA9	*	89	31	*	89	*	*	*	*	*	*	*
XA10	*	91	33	*	91	*	*	*	*	*	*	*
XA11	*	37	35	*	37	*	*	*	*	*	*	*
XA12	*	97	30	*	97	*	*	*	*	*	*	*
XA13	*	36	32	*	36	*	*	*	*	*	*	*
XA14	*	94	34	*	94	*	*	*	*	*	*	*
XA15	*	32	36	*	32	*	*	*	*	*	*	*
LOCAL PROCESSOR DATA BUS (X)												
XD0	*	13	68	*	13	*	*	*	*	*	*	*
XD1	*	75	69	*	75	*	*	*	*	*	*	*
XD2	*	71	7	*	71	*	*	*	*	*	*	*
XD3	*	8	8	*	8	*	*	*	*	*	*	*
XD4	*	68	70	*	68	*	*	*	*	*	*	*
XD5	*	5	71	*	5	*	*	*	*	*	*	*
XD6	*	12	9	*	12	*	*	*	*	*	*	*
XD7	*	73	10	*	73	*	*	*	*	*	*	*

Fig B-1 Motherboard Wiring List.

	J2	J3	J5	J7	J9	J15	J16	J17	J18	J19	J20	J21
--	----	----	----	----	----	-----	-----	-----	-----	-----	-----	-----

LOCAL PROCESSOR CONTROL SIGNALS (X)

XWR	*	23	117	*	23	*	*	*	*	*	*	*
XRFSH	*	35	*	*	*	*	*	*	*	*	*	*
XRD	*	116	111	*	116	*	*	*	*	*	*	*
XML	*	115	*	*	115	*	*	*	*	*	*	*
XMREQ	*	85	110	*	*	*	*	*	*	*	*	*
XIORQ	*	4	*	*	4	*	*	*	*	*	*	*
XWAIT	*	119	55	*	*	*	*	*	*	*	*	*
XINT	*	79	*	*	79	*	*	*	*	*	*	*
XRESET	*	10	*	*	31	*	*	*	*	*	5	*
XCLK	39	99	*	*	99	*	*	*	*	*	*	*
XCLK/2	*	118	56	*	*	*	*	*	*	*	*	*

LOCAL PROCESSOR MONITOR CHANNEL (X)

XTxD	*	15	*	*	*	*	*	*	2	*	*	*
XRxD	*	7	*	*	*	*	*	*	3	*	*	*
XRTS	*	14	*	*	*	*	*	*	4	*	*	*
XCTS	*	11	*	*	*	*	*	*	5	*	*	*
XDSR	*	74	*	*	*	*	*	*	6	*	*	*
XGND	*	64	*	*	*	*	*	*	7	*	*	*
XLSD	*	80	*	*	*	*	*	*	8	*	*	*
XDTR	*	76	*	*	*	*	*	*	20	*	*	*

NETWORK PROCESSOR ADDRESS BUS (Y)

YA0	103	*	100	103	*	*	*	*	*	*	*	*
YA1	102	*	102	102	*	*	*	*	*	*	*	*
YA2	101	*	104	101	*	*	*	*	*	*	*	*
YA3	100	*	106	100	*	*	*	*	*	*	*	*
YA4	98	*	101	98	*	*	*	*	*	*	*	*
YA5	29	*	103	29	*	*	*	*	*	*	*	*
YA6	30	*	105	30	*	*	*	*	*	*	*	*
YA7	26	*	107	26	*	*	*	*	*	*	*	*
YA8	27	*	39	*	*	*	*	*	*	*	*	*
YA9	89	*	41	*	*	*	*	*	*	*	*	*
YA10	91	*	43	*	*	*	*	*	*	*	*	*
YA11	37	*	45	*	*	*	*	*	*	*	*	*
YA12	97	*	40	*	*	*	*	*	*	*	*	*
YA13	36	*	42	*	*	*	*	*	*	*	*	*
YA14	94	*	44	*	*	*	*	*	*	*	*	*
YA15	32	*	46	*	*	*	*	*	*	*	*	*

NETWORK PROCESSOR DATA BUS (Y)

YD0	13	*	74	13	*	*	*	*	*	*	*	*
YD1	75	*	75	75	*	*	*	*	*	*	*	*

Fig B-1 Motherboard Wiring List (cont).

	J2	J3	J5	J7	J9	J15	J16	J17	J18	J19	J20	J21
YD2	71	*	13	71	*	*	*	*	*	*	*	*
YD3	8	*	14	8	*	*	*	*	*	*	*	*
YD4	68	*	76	68	*	*	*	*	*	*	*	*
YD5	5	*	77	5	*	*	*	*	*	*	*	*
YD6	12	*	15	12	*	*	*	*	*	*	*	*
YD7	73	*	16	73	*	*	*	*	*	*	*	*

NETWORK PROCESSOR CONTROL SIGNALS (Y)

YWR	23	*	119	23	*	*	*	*	*	*	*	*
YRFSH	35	*	*	*	*	*	*	*	*	*	*	*
YRD	116	*	113	116	*	*	*	*	*	*	*	*
YWAIT	119	*	57	119	*	*	*	*	*	*	*	*
YML	115	*	*	115	*	*	*	*	*	*	*	*
YMRQ	85	*	112	85	*	*	*	*	*	*	*	*
YIORQ	4	*	*	4	*	*	*	*	*	*	*	*
YINT	79	*	*	79	*	*	*	*	*	*	*	*
YRESET	10	*	*	31	*	*	*	*	*	*	*	10
YCLK	99	*	*	99	*	*	*	*	*	*	*	*
YCLK/2	118	*	58	*	*	*	*	*	*	*	*	*

NETWORK PROCESSOR MONITOR CHANNEL (Y)

YTxD	15	*	*	*	*	*	2	*	*	*	*	*
YRxD	7	*	*	*	*	*	3	*	*	*	*	*
YRTS	14	*	*	*	*	*	4	*	*	*	*	*
YCCTS	11	*	*	*	*	*	5	*	*	*	*	*
YDSR	74	*	*	*	*	*	6	*	*	*	*	*
YGND	64	*	*	*	*	*	7	*	*	*	*	*
YLSD	80	*	*	*	*	*	8	*	*	*	*	*
YDTR	76	*	*	*	*	*	20	*	*	*	*	*

LOCAL CHANNEL 1

TxD	*	*	*	*	57	*	*	*	*	*	*	2
RxD	*	*	*	*	58	*	*	*	*	*	*	3
RTS	*	*	*	*	52	*	*	*	*	*	*	4
CTS	*	*	*	*	53	*	*	*	*	*	*	5
DSR	*	*	*	*	54	*	*	*	*	*	*	6
LSD	*	*	*	*	56	*	*	*	*	*	*	8
DTR	*	*	*	*	55	*	*	*	*	*	*	20

LOCAL CHANNEL 2

TxD	*	*	*	*	49	*	*	*	*	2	*	*
RxD	*	*	*	*	50	*	*	*	*	3	*	*
RTS	*	*	*	*	44	*	*	*	*	4	*	*
CTS	*	*	*	*	45	*	*	*	*	5	*	*

Fig B-1 Motherboard Wiring List (cont).

	J2	J3	J5	J7	J9	J15	J16	J17	J18	J19	J20	J21
DSR	*	*	*	*	46	*	*	*	*	6	*	*
LSD	*	*	*	*	48	*	*	*	*	8	*	*
DTR	*	*	*	*	47	*	*	*	*	20	*	*

LOCAL CHANNEL 3

TxD	*	*	*	*	37	*	*	2	*	*	*	*
RxD	*	*	*	*	38	*	*	3	*	*	*	*
RTS	*	*	*	*	32	*	*	4	*	*	*	*
CTS	*	*	*	*	33	*	*	5	*	*	*	*
DSR	*	*	*	*	34	*	*	6	*	*	*	*
LSD	*	*	*	*	36	*	*	8	*	*	*	*
DTR	*	*	*	*	35	*	*	20	*	*	*	*

LOCAL CHANNEL 4

TxD	*	*	*	*	19	2	*	*	*	*	*	*
RxD	*	*	*	*	20	3	*	*	*	*	*	*
RTS	*	*	*	*	14	4	*	*	*	*	*	*
CTS	*	*	*	*	15	5	*	*	*	*	*	*
DSR	*	*	*	*	16	6	*	*	*	*	*	*
LSD	*	*	*	*	18	8	*	*	*	*	*	*
DTR	*	*	*	*	17	20	*	*	*	*	*	*

Fig B-1 Motherboard Wiring List (cont).

In addition to the wiring connections listed above, each MCB processor card has a number of jumper connections on its edge connector. See the Z80 MCB User's Manual (27) for further information.

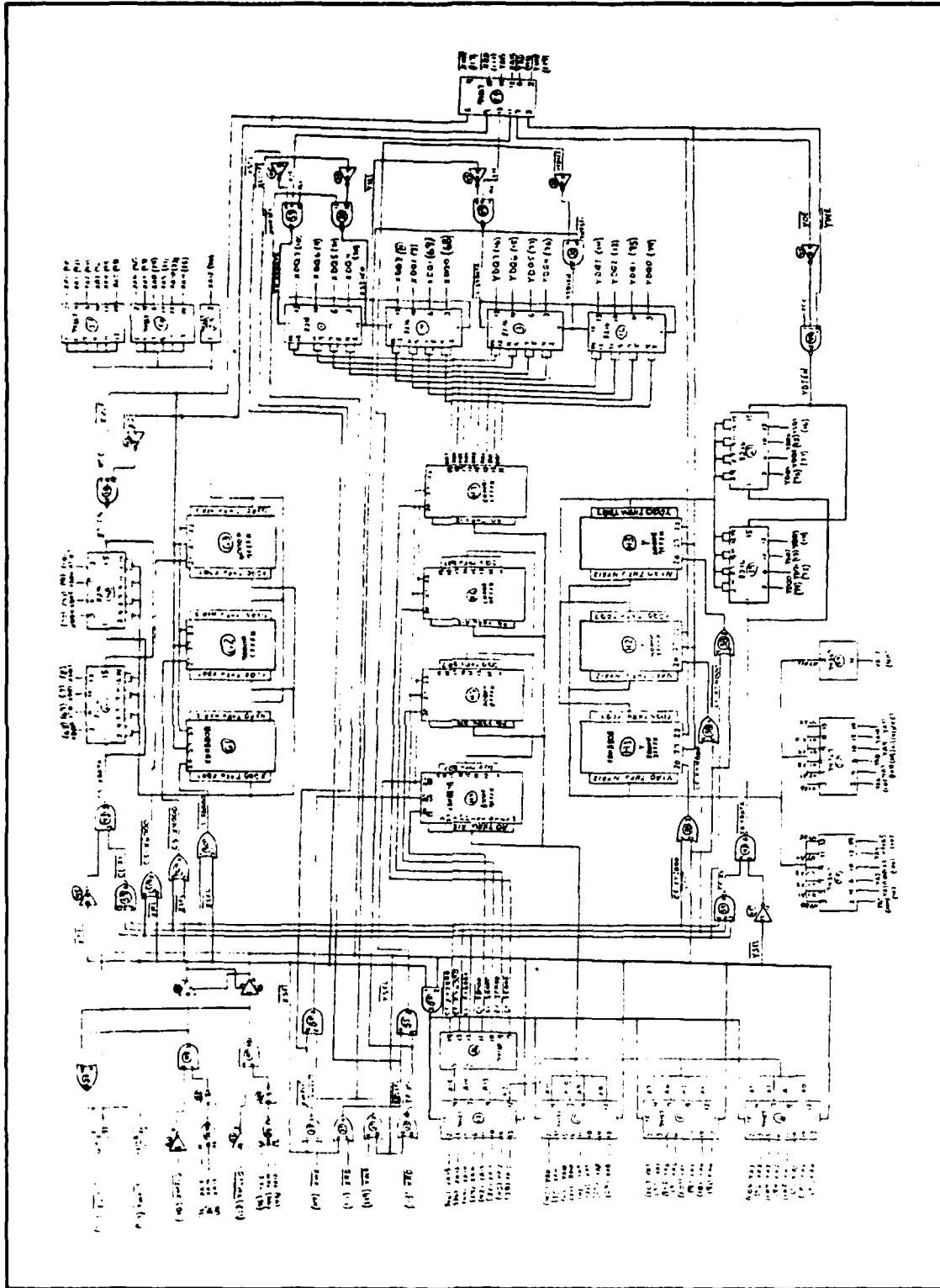


Fig B-2 Memory Card Schematic.

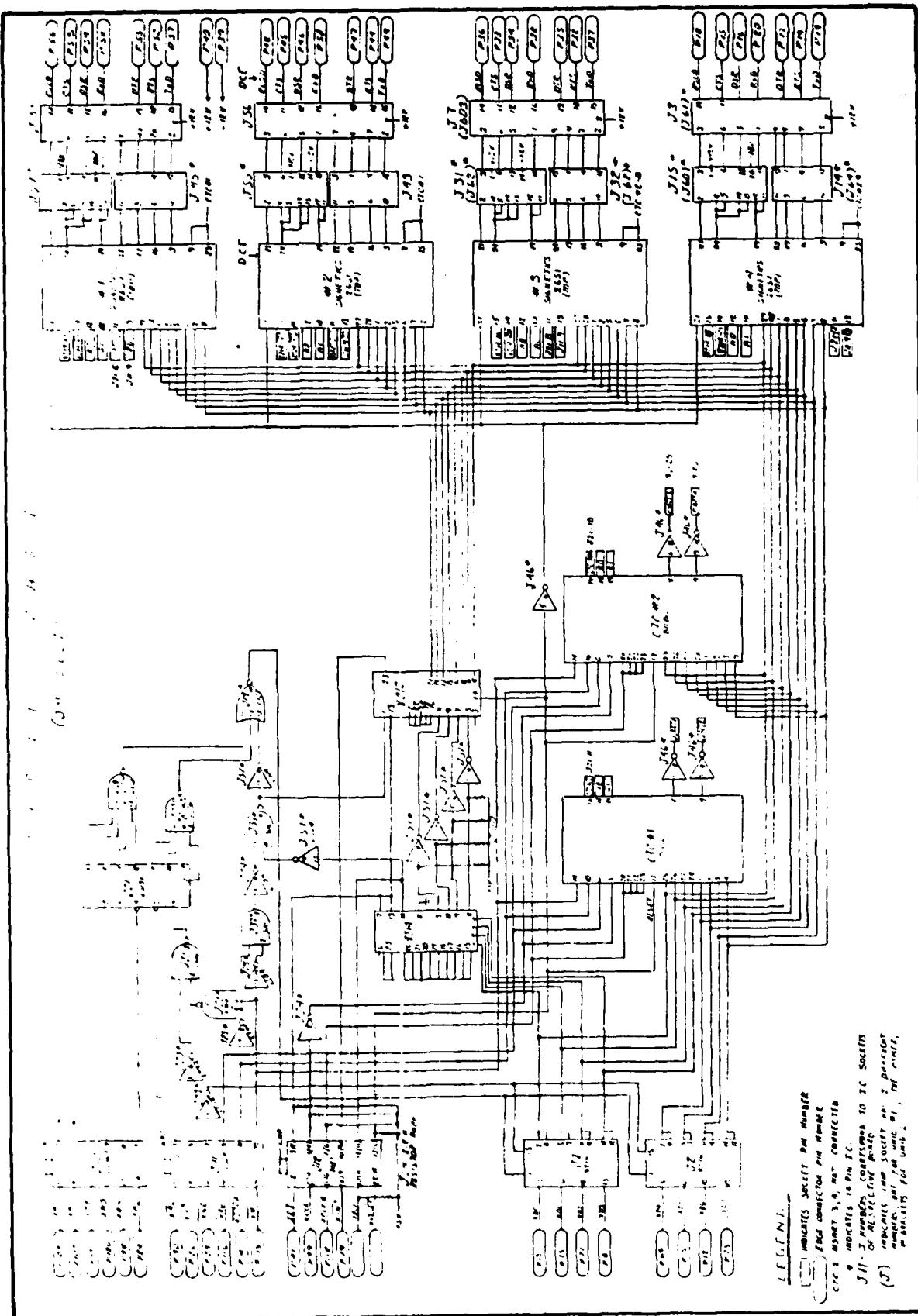


Fig B-3 Local Card Schematic.

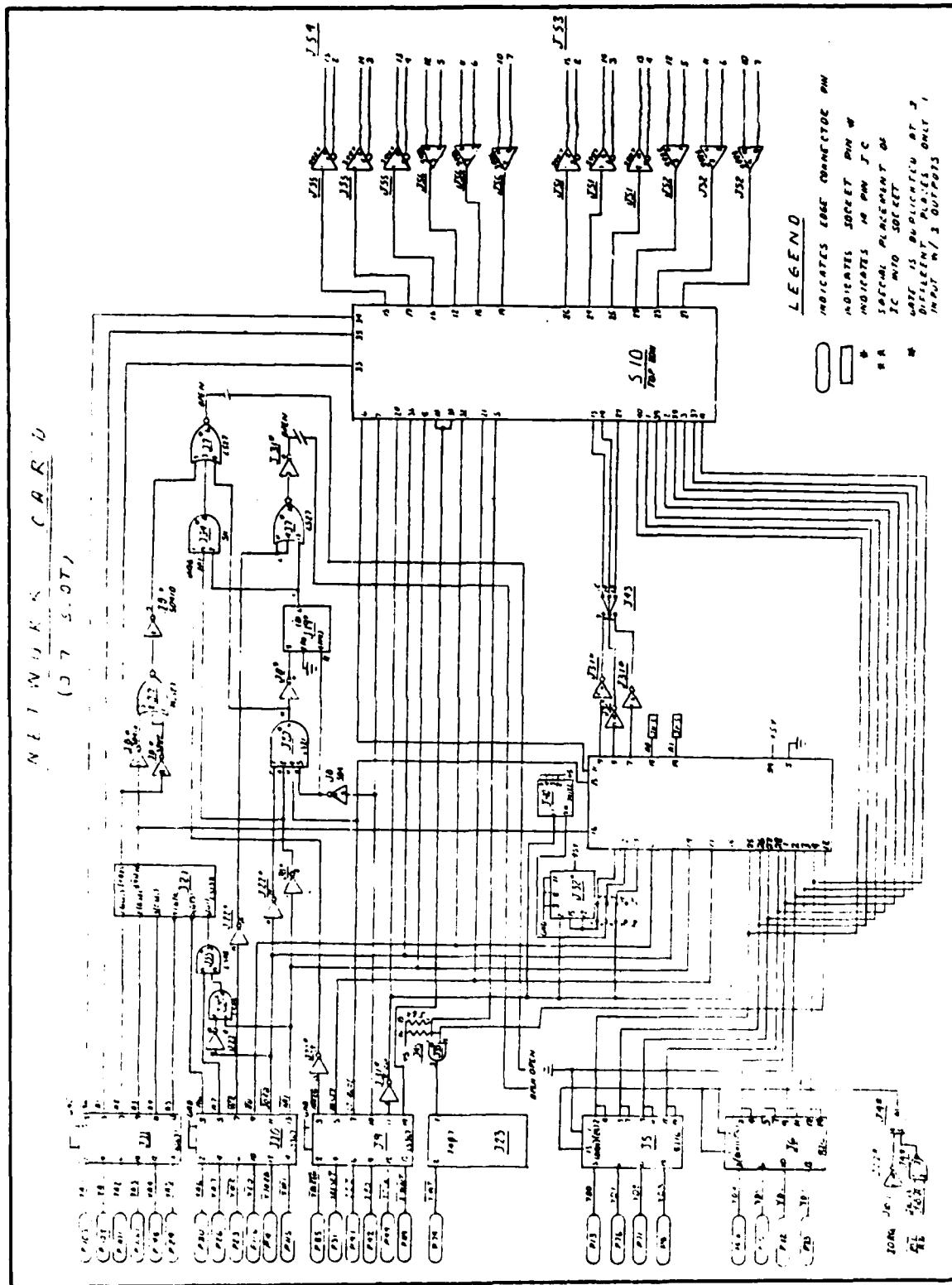


Fig B-4 Network Card Schematic.

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Appendix C

Wiring List Program

This appendix contains the wire list users manual which was used to generate the wire routing program included at the end of this appendix. The card deck which must be loaded into the CDC computer may be obtained from Dr. Lamont, AFIT/ENG. That program must be loaded before the users' program can be run.

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WLIST USERS MANUAL

I. General Description

The purpose of WLIST is to aid the hardware designer in generating an error free wire list, provide a part of the standard documentation of hardware design, and allow much simplified updating of documentation after a change in design has been made.

How It Works - The user provides a list of signal connections to each IC, plug, jack or other similar device. The data is sorted and collated in several different ways to provide the various output formats. An approximation of the best sequence of connections for each signal is generated. Errors of certain types can be detected and diagnostic messages are issued.

Output Forms - There are three output products. The first is essentially a reformatting of the input data. By unit (IC, etc.), the pin numbers and signals connected are listed. The second product is a list of all unit/pin connections by signal name, starting with the source of the signal. Also listed is the fan-out of each signal. The third product is a connection by connection wiring list, with separate lists for each level of wire wrap.

II. How to Use the Program

Input Cards - There are three types of data card: 1) the title card, 2) unit cards, and 3) connection cards.

The title card contains an asterisk followed by a title of up to 20 characters. The title is printed on each page of the output listing.

example *PROM BOARD

Unit cards contain the location, number of pins, and name (or comment) of each IC, connector, etc., on the board. One unit card is required per device. The first character is a dollar sign; followed by location (e.g. A:4), number of pins (1-999) and up to 10 comment characters.

example \$A:4,24,EPROM 2708

Connection cards contain the names of signals to be connected to each pin of a device defined by a unit card. As many connection cards as necessary follow each unit card. Signal names of up to 10 characters are listed, separated by commas, starting with pin 1. Pins intended to have no connection must be named "NC". One signal source must be specified for each signal name used on a board. The source is identified by an asterisk preceding the signal name. Connection cards may only use the first 72 columns. Columns 73 through 80 are reserved for optional sequence numbers.

example \$D:8,14,AND 7408

ENAL,CLK,*STB1,ENA2,CLK,*STB2,
GND,NC,NC,NC,NC,NC,NC,VCC

Executing the Program

WLIST can be run using a card reader or a time-sharing terminal.

If run using a card reader, the following control card deck should be used.

```
$JOB H80 SYST BCDDMP PRI=15 OUT=0  
*RJE 100 H80 *  
3 initials,T15,CM77000,IO20,.T820665,name,box #,phone #  
ATTACH,WLIST,ID=E770050,SN=ASDEN,CY=1.  
LIBRARY,COBOL.  
COPY,INPUT,WLDATA.  
REWIND,WLDATA,WLIST.  
WLIST.  
REWIND,WLDATA,WLIST.
```

7/8/9

data cards

6/7/8/9 See Fig C-1 for a sample card deck.

If executed from a time-sharing terminal, the "deck" should contain the same control cards used above, with "*EOR" substituted for "7/8/9" and "*EOF" substituted for "6/7/8/9".

III. Interpreting the Output

Two header pages are printed identifying the circuit, version of WLIST, and the date and time at which the job was run. This allows immediate identification of the most recent run.

The normal output is self-explanatory. Signal sources are identified by a leading asterisk. The wire list output is provided in wire wrap levels. All level one connections should be made prior to proceeding to level two. This will eliminate wiring level changes and make later modification of

```
$JOB H80 SYST BCDDMP PRI=15 OUT=0
*RJE 100 H80 *
GFC,T15,CM77000,IO20,.T820665,CUOMO,4093,55533
ATTACH,WLIST, ID=E770050,SN=ASDEN,CY=1.
LIBRARY,COBOL.
COPY,INPUT,WLDATA.
REWIND,WLDATA,WLIST.
WLIST.
REWIND,WLDATA,WLIST.
7/8/9
*WLIST EXAMPLE
$A:1,16,CNTR 74161
CLR,CLK,D4,D5,D6,D7,ENA,GND,
LD*,ENA,A0,A1,A2,A3,*C1,VCC
$B:1,16,CNTR 74161
CLR,CLK,D0,D1,D2,D3,C1,GND,
LD*,C1,A4,A5,A6,A7,*OVR,VCC
$C:1,25,CONNECTOR
*D0,*D1,*D2,*D3,*D4,*D5,*D6,*D7,*LD*,*ENA,*CLK,NC,
*VCC,*GND,*CLR,NC,*A0,*A1,*A2,*A3,*A4,*A5,*A6,*A7,OVR
6/7/8/9
```

Fig C-1 Example Card Deck.

the circuit easier. Since the algorithm for determining the sequence is a simple one, the results may not always be the best possible. If there are signals that are sensitive to excessive wire length, their routing should be checked before the board is wired. Space is provided on the wire list to enter information such as wire gauge and color or other appropriate remarks. The list is designed to be cut down to 8 x 10 1/2 size for easy use at the lab bench.

Error Diagnostics - A moderate amount of error checking is done in the program. As with all such error diagnostics, care must be used in interpretation because the actual error may not be exactly that indicated. The commonly encountered error messages will be discussed briefly.

If a signal name occurs only once, an informative diagnostic advises that the fan-out is zero. This may result from a typographic error in the string name.

If no source is declared for a signal, an informative diagnostic advises that there is no source. This may also indicate a typographic error.

If more than one source has been declared for a signal, an informative diagnostic advises such.

If an error has been detected, the wire list will be aborted and a fatal diagnostic will be printed. This is necessary because results of the wire list are unpredictable if errors have been encountered.

IV. Conclusion

Although it will probably be more work for the designer to generate a wire list with this program, it has been found that it is useful in removing errors from the wire list and, in some cases, pointing out design errors. It forces more discipline on the designer, particularly in the often neglected area of documentation. It is of particular advantage in keeping documentation up-to-date when changes are made in the design after fabrication. The few cards affected can be changed, the program rerun, and a completely new, up-to-date set of documentation, without penciled corrections, is available. If done properly, use of the program can be well worth the time.

WIRE ROUTE LISTING

Following is the wire routing listing which was used to wire wrap the new memory boards built for the UNIDs. On this page is listed a guide to the correlation between the list's chip locations and the card's chip socket labels.

A:1 = Edge Connector	D:13 = 27	F:11 = 49
B:1 = 1	D:16 = 30	F:12 = 50
B:13 = 3	D:18 = 32	F:13 = 51
B:16 = 6	D:21 = 34	F:14 = 52
B:18 = 8	D:23 = 36	F:15 = 53
B:21 = 10	E:11 = 37	F:16 = 54
B:23 = 12	E:12 = 38	F:17 = 55
C:12 = 14	E:13 = 39	F:18 = 56
C:14 = 16	E:15 = 41	F:19 = 57
C:17 = 19	E:17 = 43	F:21 = 58
	E:19 = 45	F:22 = 59
	E:23 = 48	F:23 = 60

\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$
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\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$
\$\$\$\$\$\$\$\$WIRELIST PROGRAM \$\$\$\$\$
\$\$\$\$\$VERSION 3.1-(MAY 18, 1978)\$\$\$\$\$
\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$
\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$
\$\$\$\$\$\$\$\$WIRELIST FOR: \$\$\$\$\$
\$\$\$\$\$UNID MEMORY CARD \$\$\$\$\$
\$\$\$\$ 11/28/92 15.11.26. \$\$\$\$\$
\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$
\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$
\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$\$

UNIT CONNECTIONS FOR U102 MEMORY CARD

PAGE 1

```

#1:1
#F DCE 21.5
# 1 : C
# 2 : C 6*YD06 17 IC 25 IC 33*YA10 41*YA9
# 3 : C 10*YD07 18 IC 26 NC 34*XA14 42*YA13
# 4 : C 21 C 19 IC 27 IC 35*XA11 43*YA10
# 5 : C 12 C 20 IC 28 NC 36*XA15 44*YA14
# 6 : C 13*YD02 21 IC 29*XA8 37 IC .
# 7 : C 14*YD03 22 IC 30*XA12 38 NC 45*YA11
# 8 : C 15*YD06 23 NC 31*XA9 39 NC 46*YA15
# 9 : C 16*YD07 24 NC 32*XA13 40*YA12 47 NC
# 10 : XDG3 25 NC 41*XA11 48 NC
# 11 : XDG3 26 NC 42*XA10 49 NC
# 12 : XDG3 27 NC 43*XA13 50 NC
# 13 : XDG3 28 NC 44*XA12 51 NC
# 14 : XDG3 29 NC 45*XA11 52 NC
# 15 : XDG3 30 NC 46*YA15 53 NC
# 16 : XDG3 31 NC 47 NC 54 NC
# 17 : XDG3 32 NC 48 NC 55 NC
# 18 : XDG3 33 NC 49 NC 56 NC
# 19 : XDG3 50 NC 57 YA11 65 NC 73 NC 81 NC
# 20 : XDG3 51 NC 58 YCLK/2 66 NC 74*YD00 82 NC 39 NC
# 21 : XDG3 52 NC 59 C 67 IC 75*YD01 83 IC 40*XA0
# 22 : XDG3 53 NC 60*VCC 68*XD00 76*YD04 84 NC 91*XA4
# 23 : XDG3 54 NC 61 C 69*XD01 77*YD05 85 IC 92*XA1
# 24 : XDG3 55 NC 62 C 70*XD04 78 IC 86 NC 93*XA5
# 25 : XDG3 56 NC 63 C 71*XD05 79 IC 87 IC 94*XA2
# 26 : XDG3 57 NC 64 C 80 IC 88 NC 95*XA6
# 27 : XDG3 58 NC 65 C 81 IC 89 NC 96*XA3
# 28 : XDG3 59 NC 66 C 82 IC 90 NC
# 29 : XDG3 60 NC 67 C 83 IC 91 NC
# 30 : XDG3 61 NC 68 C 84 IC 92 NC
# 31 : XDG3 62 NC 69 C 85 IC 93 NC
# 32 : XDG3 63 NC 70 C 86 IC 94 NC
# 33 : XDG3 64 NC 71 C 87 IC 95 NC
# 34 : XDG3 65 NC 72 C 88 IC 96 NC
# 35 : XDG3 66 NC 73 C 89 IC 97 NC
# 36 : XDG3 67 NC 74 C 90 IC 98 NC
# 37 : XDG3 68 NC 75 C 91 IC 99 NC
# 38 : XDG3 69 NC 76 C 92 IC 100 NC
# 39 : XDG3 70 NC 77 C 93 IC 101 NC
# 40 : XDG3 71 NC 78 C 94 IC 102 NC
# 41 : XDG3 72 NC 79 C 95 IC 103 NC
# 42 : XDG3 73 NC 80 C 96 IC 104 NC
# 43 : XDG3 74 NC 81 C 97 IC 105 NC
# 44 : XDG3 75 NC 82 C 98 IC 106 NC
# 45 : XDG3 76 NC 83 C 99 IC 107 NC
# 46 : XDG3 77 NC 84 C 108 C 108*YA5
# 47 : XDG3 78 NC 85 C 109 C 109*YA6
# 48 : XDG3 79 NC 86 C 110 C 110*YA7
# 49 : XDG3 80 NC 87 C 111 C 111*YA8
# 50 : XDG3 81 NC 88 C 112 C 112*YA9
# 51 : XDG3 82 NC 89 C 113 C 113*YA10
# 52 : XDG3 83 NC 90 C 114 C 114*YA11
# 53 : XDG3 84 NC 91 C 115 C 115*YA12
# 54 : XDG3 85 NC 92 C 116 C 116*YA13
# 55 : XDG3 86 NC 93 C 117 C 117*YA14
# 56 : XDG3 87 NC 94 C 118 C 118*YA15
# 57 : XDG3 88 NC 95 C 119 C 119*YA16
# 58 : XDG3 89 NC 96 C 120 C 120*YA17
# 59 : XDG3 90 NC 97 C 121 C 121*YA18
# 60 : XDG3 91 NC 98 C 122 C 122*YA19
# 61 : XDG3 92 NC 99 C 123 C 123*YA20
# 62 : XDG3 93 NC 100 C 124 C 124*YA21
# 63 : XDG3 94 NC 101 C 125 C 125*YA22
# 64 : XDG3 95 NC 102 C 126 C 126*YA23
# 65 : XDG3 96 NC 103 C 127 C 127*YA24
# 66 : XDG3 97 NC 104 C 128 C 128*YA25
# 67 : XDG3 98 NC 105 C 129 C 129*YA26
# 68 : XDG3 99 NC 106 C 130 C 130*YA27
# 69 : XDG3 100 NC 107 C 131 C 131*YA28
# 70 : XDG3 101 NC 108 C 132 C 132*YA29
# 71 : XDG3 102 NC 109 C 133 C 133*YA30
# 72 : XDG3 103 NC 110 C 134 C 134*YA31
# 73 : XDG3 104 NC 111 C 135 C 135*YA32
# 74 : XDG3 105 NC 112 C 136 C 136*YA33
# 75 : XDG3 106 NC 113 C 137 C 137*YA34
# 76 : XDG3 107 NC 114 C 138 C 138*YA35
# 77 : XDG3 108 NC 115 C 139 C 139*YA36
# 78 : XDG3 109 NC 116 C 140 C 140*YA37
# 79 : XDG3 110 NC 117 C 141 C 141*YA38
# 80 : XDG3 111 NC 118 C 142 C 142*YA39
# 81 : XDG3 112 NC 119 C 143 C 143*YA40
# 82 : XDG3 113 NC 120 C 144 C 144*YA41
# 83 : XDG3 114 NC 121 C 145 C 145*YA42
# 84 : XDG3 115 NC 122 C 146 C 146*YA43
# 85 : XDG3 116 NC 123 C 147 C 147*YA44
# 86 : XDG3 117 NC 124 C 148 C 148*YA45
# 87 : XDG3 118 NC 125 C 149 C 149*YA46
# 88 : XDG3 119 NC 126 C 150 C 150*YA47
# 89 : XDG3 120 NC 127 C 151 C 151*YA48
# 90 : XDG3 121 NC 128 C 152 C 152*YA49
# 91 : XDG3 122 NC 129 C 153 C 153*YA50
# 92 : XDG3 123 NC 130 C 154 C 154*YA51
# 93 : XDG3 124 NC 131 C 155 C 155*YA52
# 94 : XDG3 125 NC 132 C 156 C 156*YA53
# 95 : XDG3 126 NC 133 C 157 C 157*YA54
# 96 : XDG3 127 NC 134 C 158 C 158*YA55
# 97 : XDG3 128 NC 135 C 159 C 159*YA56
# 98 : XDG3 129 NC 136 C 160 C 160*YA57
# 99 : XDG3 130 NC 137 C 161 C 161*YA58
# 100 : XDG3 131 NC 138 C 162 C 162*YA59
# 101 : XDG3 132 NC 139 C 163 C 163*YA60
# 102 : XDG3 133 NC 140 C 164 C 164*YA61
# 103 : XDG3 134 NC 141 C 165 C 165*YA62
# 104 : XDG3 135 NC 142 C 166 C 166*YA63
# 105 : XDG3 136 NC 143 C 167 C 167*YA64
# 106 : XDG3 137 NC 144 C 168 C 168*YA65
# 107 : XDG3 138 NC 145 C 169 C 169*YA66
# 108 : XDG3 139 NC 146 C 170 C 170*YA67
# 109 : XDG3 140 NC 147 C 171 C 171*YA68
# 110 : XDG3 141 NC 148 C 172 C 172*YA69
# 111 : XDG3 142 NC 149 C 173 C 173*YA70
# 112 : XDG3 143 NC 150 C 174 C 174*YA71
# 113 : XDG3 144 NC 151 C 175 C 175*YA72
# 114 : XDG3 145 NC 152 C 176 C 176*YA73
# 115 : XDG3 146 NC 153 C 177 C 177*YA74
# 116 : XDG3 147 NC 154 C 178 C 178*YA75
# 117 : XDG3 148 NC 155 C 179 C 179*YA76
# 118 : XDG3 149 NC 156 C 180 C 180*YA77
# 119 : XDG3 150 NC 157 C 181 C 181*YA78
# 120 : XDG3 151 NC 158 C 182 C 182*YA79
# 121 : XDG3 152 NC 159 C 183 C 183*YA80
# 122 : XDG3 153 NC 160 C 184 C 184*YA81
# 123 : XDG3 154 NC 161 C 185 C 185*YA82
# 124 : XDG3 155 NC 162 C 186 C 186*YA83
# 125 : XDG3 156 NC 163 C 187 C 187*YA84
# 126 : XDG3 157 NC 164 C 188 C 188*YA85
# 127 : XDG3 158 NC 165 C 189 C 189*YA86
# 128 : XDG3 159 NC 166 C 190 C 190*YA87
# 129 : XDG3 160 NC 167 C 191 C 191*YA88
# 130 : XDG3 161 NC 168 C 192 C 192*YA89
# 131 : XDG3 162 NC 169 C 193 C 193*YA90
# 132 : XDG3 163 NC 170 C 194 C 194*YA91
# 133 : XDG3 164 NC 171 C 195 C 195*YA92
# 134 : XDG3 165 NC 172 C 196 C 196*YA93
# 135 : XDG3 166 NC 173 C 197 C 197*YA94
# 136 : XDG3 167 NC 174 C 198 C 198*YA95
# 137 : XDG3 168 NC 175 C 199 C 199*YA96
# 138 : XDG3 169 NC 176 C 200 C 200*YA97
# 139 : XDG3 170 NC 177 C 201 C 201*YA98
# 140 : XDG3 171 NC 178 C 202 C 202*YA99
# 141 : XDG3 172 NC 179 C 203 C 203*YA100
# 142 : XDG3 173 NC 180 C 204 C 204*YA101
# 143 : XDG3 174 NC 181 C 205 C 205*YA102
# 144 : XDG3 175 NC 182 C 206 C 206*YA103
# 145 : XDG3 176 NC 183 C 207 C 207*YA104
# 146 : XDG3 177 NC 184 C 208 C 208*YA105
# 147 : XDG3 178 NC 185 C 209 C 209*YA106
# 148 : XDG3 179 NC 186 C 210 C 210*YA107
# 149 : XDG3 180 NC 187 C 211 C 211*YA108
# 150 : XDG3 181 NC 188 C 212 C 212*YA109
# 151 : XDG3 182 NC 189 C 213 C 213*YA110
# 152 : XDG3 183 NC 190 C 214 C 214*YA111
# 153 : XDG3 184 NC 191 C 215 C 215*YA112
# 154 : XDG3 185 NC 192 C 216 C 216*YA113
# 155 : XDG3 186 NC 193 C 217 C 217*YA114
# 156 : XDG3 187 NC 194 C 218 C 218*YA115
# 157 : XDG3 188 NC 195 C 219 C 219*YA116
# 158 : XDG3 189 NC 196 C 220 C 220*YA117
# 159 : XDG3 190 NC 197 C 221 C 221*YA118
# 160 : XDG3 191 NC 198 C 222 C 222*YA119
# 161 : XDG3 192 NC 199 C 223 C 223*YA120
# 162 : XDG3 193 NC 200 C 224 C 224*YA121
# 163 : XDG3 194 NC 201 C 225 C 225*YA122
# 164 : XDG3 195 NC 202 C 226 C 226*YA123
# 165 : XDG3 196 NC 203 C 227 C 227*YA124
# 166 : XDG3 197 NC 204 C 228 C 228*YA125
# 167 : XDG3 198 NC 205 C 229 C 229*YA126
# 168 : XDG3 199 NC 206 C 230 C 230*YA127
# 169 : XDG3 200 NC 207 C 231 C 231*YA128
# 170 : XDG3 201 NC 208 C 232 C 232*YA129
# 171 : XDG3 202 NC 209 C 233 C 233*YA130
# 172 : XDG3 203 NC 210 C 234 C 234*YA131
# 173 : XDG3 204 NC 211 C 235 C 235*YA132
# 174 : XDG3 205 NC 212 C 236 C 236*YA133
# 175 : XDG3 206 NC 213 C 237 C 237*YA134
# 176 : XDG3 207 NC 214 C 238 C 238*YA135
# 177 : XDG3 208 NC 215 C 239 C 239*YA136
# 178 : XDG3 209 NC 216 C 240 C 240*YA137
# 179 : XDG3 210 NC 217 C 241 C 241*YA138
# 180 : XDG3 211 NC 218 C 242 C 242*YA139
# 181 : XDG3 212 NC 219 C 243 C 243*YA140
# 182 : XDG3 213 NC 220 C 244 C 244*YA141
# 183 : XDG3 214 NC 221 C 245 C 245*YA142
# 184 : XDG3 215 NC 222 C 246 C 246*YA143
# 185 : XDG3 216 NC 223 C 247 C 247*YA144
# 186 : XDG3 217 NC 224 C 248 C 248*YA145
# 187 : XDG3 218 NC 225 C 249 C 249*YA146
# 188 : XDG3 219 NC 226 C 250 C 250*YA147
# 189 : XDG3 220 NC 227 C 251 C 251*YA148
# 190 : XDG3 221 NC 228 C 252 C 252*YA149
# 191 : XDG3 222 NC 229 C 253 C 253*YA150
# 192 : XDG3 223 NC 230 C 254 C 254*YA151
# 193 : XDG3 224 NC 231 C 255 C 255*YA152
# 194 : XDG3 225 NC 232 C 256 C 256*YA153
# 195 : XDG3 226 NC 233 C 257 C 257*YA154
# 196 : XDG3 227 NC 234 C 258 C 258*YA155
# 197 : XDG3 228 NC 235 C 259 C 259*YA156
# 198 : XDG3 229 NC 236 C 260 C 260*YA157
# 199 : XDG3 230 NC 237 C 261 C 261*YA158
# 200 : XDG3 231 NC 238 C 262 C 262*YA159
# 201 : XDG3 232 NC 239 C 263 C 263*YA160
# 202 : XDG3 233 NC 240 C 264 C 264*YA161
# 203 : XDG3 234 NC 241 C 265 C 265*YA162
# 204 : XDG3 235 NC 242 C 266 C 266*YA163
# 205 : XDG3 236 NC 243 C 267 C 267*YA164
# 206 : XDG3 237 NC 244 C 268 C 268*YA165
# 207 : XDG3 238 NC 245 C 269 C 269*YA166
# 208 : XDG3 239 NC 246 C 270 C 270*YA167
# 209 : XDG3 240 NC 247 C 271 C 271*YA168
# 210 : XDG3 241 NC 248 C 272 C 272*YA169
# 211 : XDG3 242 NC 249 C 273 C 273*YA170
# 212 : XDG3 243 NC 250 C 274 C 274*YA171
# 213 : XDG3 244 NC 251 C 275 C 275*YA172
# 214 : XDG3 245 NC 252 C 276 C 276*YA173
# 215 : XDG3 246 NC 253 C 277 C 277*YA174
# 216 : XDG3 247 NC 254 C 278 C 278*YA175
# 217 : XDG3 248 NC 255 C 279 C 279*YA176
# 218 : XDG3 249 NC 256 C 280 C 280*YA177
# 219 : XDG3 250 NC 257 C 281 C 281*YA178
# 220 : XDG3 251 NC 258 C 282 C 282*YA179
# 221 : XDG3 252 NC 259 C 283 C 283*YA180
# 222 : XDG3 253 NC 260 C 284 C 284*YA181
# 223 : XDG3 254 NC 261 C 285 C 285*YA182
# 224 : XDG3 255 NC 262 C 286 C 286*YA183
# 225 : XDG3 256 NC 263 C 287 C 287*YA184
# 226 : XDG3 257 NC 264 C 288 C 288*YA185
# 227 : XDG3 258 NC 265 C 289 C 289*YA186
# 228 : XDG3 259 NC 266 C 290 C 290*YA187
# 229 : XDG3 260 NC 267 C 291 C 291*YA188
# 230 : XDG3 261 NC 268 C 292 C 292*YA189
# 231 : XDG3 262 NC 269 C 293 C 293*YA190
# 232 : XDG3 263 NC 270 C 294 C 294*YA191
# 233 : XDG3 264 NC 271 C 295 C 295*YA192
# 234 : XDG3 265 NC 272 C 296 C 296*YA193
# 235 : XDG3 266 NC 273 C 297 C 297*YA194
# 236 : XDG3 267 NC 274 C 298 C 298*YA195
# 237 : XDG3 268 NC 275 C 299 C 299*YA196
# 238 : XDG3 269 NC 276 C 300 C 300*YA197
# 239 : XDG3 270 NC 277 C 301 C 301*YA198
# 240 : XDG3 271 NC 278 C 302 C 302*YA199
# 241 : XDG3 272 NC 279 C 303 C 303*YA200
# 242 : XDG3 273 NC 280 C 304 C 304*YA201
# 243 : XDG3 274 NC 281 C 305 C 305*YA202
# 244 : XDG3 275 NC 282 C 306 C 306*YA203
# 245 : XDG3 276 NC 283 C 307 C 307*YA204
# 246 : XDG3 277 NC 284 C 308 C 308*YA205
# 247 : XDG3 278 NC 285 C 309 C 309*YA206
# 248 : XDG3 279 NC 286 C 310 C 310*YA207
# 249 : XDG3 280 NC 287 C 311 C 311*YA208
# 250 : XDG3 281 NC 288 C 312 C 312*YA209
# 251 : XDG3 282 NC 289 C 313 C 313*YA210
# 252 : XDG3 283 NC 290 C 314 C 314*YA211
# 253 : XDG3 284 NC 291 C 315 C 315*YA212
# 254 : XDG3 285 NC 292 C 316 C 316*YA213
# 255 : XDG3 286 NC 293 C 317 C 317*YA214
# 256 : XDG3 287 NC 294 C 318 C 318*YA215
# 257 : XDG3 288 NC 295 C 319 C 319*YA216
# 258 : XDG3 289 NC 296 C 320 C 320*YA217
# 259 : XDG3 290 NC 297 C 321 C 321*YA218
# 260 : XDG3 291 NC 298 C 322 C 322*YA219
# 261 : XDG3 292 NC 299 C 323 C 323*YA220
# 262 : XDG3 293 NC 300 C 324 C 324*YA221
# 263 : XDG3 294 NC 301 C 325 C 325*YA222
# 264 : XDG3 295 NC 302 C 326 C 326*YA223
# 265 : XDG3 296 NC 303 C 327 C 327*YA224
# 266 : XDG3 297 NC 304 C 328 C 328*YA225
# 267 : XDG3 298 NC 305 C 329 C 329*YA226
# 268 : XDG3 299 NC 306 C 330 C 330*YA227
# 269 : XDG3 300 NC 307 C 331 C 331*YA228
# 270 : XDG3 301 NC 308 C 332 C 332*YA229
# 271 : XDG3 302 NC 309 C 333 C 333*YA230
# 272 : XDG3 303 NC 310 C 334 C 334*YA231
# 273 : XDG3 304 NC 311 C 335 C 335*YA232
# 274 : XDG3 305 NC 312 C 336 C 336*YA233
# 275 : XDG3 306 NC 313 C 337 C 337*YA234
# 276 : XDG3 307 NC 314 C 338 C 338*YA235
# 277 : XDG3 308 NC 315 C 339 C 339*YA236
# 278 : XDG3 309 NC 316 C 340 C 340*YA237
# 279 : XDG3 310 NC 317 C 341 C 341*YA238
# 280 : XDG3 311 NC 318 C 342 C 342*YA239
# 281 : XDG3 312 NC 319 C 343 C 343*YA240
# 282 : XDG3 313 NC 320 C 344 C 344*YA241
# 283 : XDG3 314 NC 321 C 345 C 345*YA242
# 284 : XDG3 315 NC 322 C 346 C 346*YA243
# 285 : XDG3 316 NC 323 C 347 C 347*YA244
# 286 : XDG3 317 NC 324 C 348 C 348*YA245
# 287 : XDG3 318 NC 325 C 349 C 349*YA246
# 288 : XDG3 319 NC 326 C 350 C 350*YA247
# 289 : XDG3 320 NC 327 C 351 C 351*YA248
# 290 : XDG3 321 NC 328 C 352 C 352*YA249
# 291 : XDG3 322 NC 329 C 353 C 353*YA250
# 292 : XDG3 323 NC 330 C 354 C 354*YA251
# 293 : XDG3 324 NC 331 C 355 C 355*YA252
# 294 : XDG3 325 NC 332 C 356 C 356*YA253
# 295 : XDG3 326 NC 333 C 357 C 357*YA254
# 296 : XDG3 327 NC 334 C 358 C 358*YA255
# 297 : XDG3 328 NC 335 C 359 C 359*YA256
# 298 : XDG3 329 NC 336 C 360 C 360*YA257
# 299 : XDG3 330 NC 337 C 361 C 361*YA258
# 300 : XDG3 331 NC 338 C 362 C 362*YA259
# 301 : XDG3 332 NC 339 C 363 C 363*YA260
# 302 : XDG3 333 NC 340 C 364 C 364*YA261
# 303 : XDG3 334 NC 341 C 365 C 365*YA262
# 304 : XDG3 335 NC 342 C 366 C 366*YA263
# 305 : XDG3 336 NC 343 C 367 C 367*YA264
# 306 : XDG3 337 NC 344 C 368 C 368*YA265
# 307 : XDG3 338 NC 345 C 369 C 369*YA266
# 308 : XDG3 339 NC 346 C 370 C 370*YA267
# 309 : XDG3 340 NC 347 C 371 C 371*YA268
# 310 : XDG3 341 NC 348 C 372 C 372*YA269
# 311 : XDG3 342 NC 349 C 373 C 373*YA270
# 312 : XDG3 343 NC 350 C 374 C 374*YA271
# 313 : XDG3 344 NC 351 C 375 C 375*YA272
# 314 : XDG3 345 NC 352 C 376 C 376*YA273
# 315 : XDG3 346 NC 353 C 377 C 377*YA274
# 316 : XDG3 347 NC 354 C 378 C 378*YA275
# 317 : XDG3 348 NC 355 C 379 C 379*YA276
# 318 : XDG3 349 NC 356 C 380 C 380*YA277
# 319 : XDG3 350 NC 357 C 381 C 381*YA278
# 320 : XDG3 351 NC 358 C 382 C 382*YA279
# 321 : XDG3 352 NC 359 C 383 C 383*YA280
# 322 : XDG3 353 NC 360 C 384 C 384*YA281
# 323 : XDG3 354 NC 361 C 385 C 385*YA282
# 324 : XDG3 355 NC 362 C 386 C 386*YA283
# 325 : XDG3 356 NC 363 C 387 C 387*YA284
# 326 : XDG3 357 NC 364 C 388 C 388*YA285
# 327 : XDG3 358 NC 365 C 389 C 389*YA286
# 328 : XDG3 359 NC 366 C 390 C 390*YA287
# 329 : XDG3 360 NC 367 C 391 C 391*YA288
# 330 : XDG3 361 NC 368 C 392 C 392*YA289
# 331 : XDG3 362 NC 369 C 393 C 393*YA290
# 332 : XDG3 363 NC 370 C 394 C 394*YA291
# 333 : XDG3 364 NC 371 C 395 C 395*YA292
# 334 : XDG3 365 NC 372 C 396 C 396*YA293
# 335 : XDG3 366 NC 373 C 397 C 397*YA294
# 336 : XDG3 367 NC 374 C 398 C 398*YA295
# 337 : XDG3 368 NC 375 C 399 C 399*YA296
# 338 : XDG3 369 NC 376 C 400 C 400*YA297
# 339 : XDG3 370 NC 377 C 401 C 401*YA298
# 340 : XDG3 371 NC 378 C 402 C 402*YA299
# 341 : XDG3 372 NC 379 C 403
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MEMORIAL ADDRESS - E. H. COOPER

UNIVERSITY OF TORONTO FPC UNIT MEV-Y CARD

PAGE 3

#P:16	#74301,A,031	#D:18	#74C4*,CY:2	#D:21	#7427 3-N00
# 1 YXA131415	5 YFDSEL	# 1 XA131415	3 YMREQ	# 1 XA15	9 YA13
# 2 YWFEG	10 YWFSEL	# 2 XA131415	10* NYRDSEL	# 2 XA14	10 YA14
# 3 YAFHIT	11* XSUZER	# 3 YA131415	11 YRDSEL	# 3 NC	11 YA15
# 4 YMREQ	12 XWSEL	# 4 NYA131415	12* NXRDSEL	# 4 NC	12* XA131415
# 5 YXA131415	13 XFDSel	# 5 XMREQ	13 XRDSEL	# 5 NC	13 YA13
# 6 YAFHIT	14 VCC	# 6 NXMRFO	14 VCC	# 6 NC	14 VCC
# 7 GND		# 7 GND		# 7 GND	
# -*YSD:EF		# -*YMREQ		# 8*YA131415	
#E:23	#E:11	#E:11	#E:12	#E:12	#E:12
#7413*-36	#7432 2-OR	#7432 2-OR	#7432 2-OR	#7432 2-OR	#7432 2-OR
# 1 A13	9 CE-SCOC	# 1 XSFL	9 YM2	# 1 CE-XY2000	9 CE-XY6000
# 2 A14	10* CE-SAOC	# 2 XWR	10 YSEL	# 2 YSEL	10 YSEL
# 3 A15	11* CE-SEOC	# 3* XWSEL	11* YRDSEL	# 3*CS-Y2000	11 NC
# 4 GND	12* CE-XY6000	# 4 XSEL	12 YSEL	# 4 CE-XY4000	12 NC
# 5 GND	13* CE-XY4000	# 5 XRD	13 YRD	# 5 YSEL	13 NC
# 6 VCC	14* CE-XY2000	# 6* XRDSEL	14 VCC	# 6*CS-Y4000	14 VCC
# 7* CE-CERO	15 IC	# 7 GND		# 7 GND	
# 8 GND	16 VCC	# 8* YURSEL		# 8*CS-Y6000	
#E:13	#E:15	#E:15	#E:17	#E:17	#E:17
#/16 YDATA	#74126-41	#7400NAND43			
# 1 CS-YDA A	5 YSEL	# 1 AXSEL			
# 2* YDC2	10 YDC2	# 2 XAPBIT	5 NC		
# 3 YDG2	11 YDG2	# 3* XSEL	10 NC		
# 4 YD2C	12* YD23	# 4 YSEL	# 2 CE-XY	10 NC	
# 5 YD1	13 YD23	# 5 YAFRIT	# 3*CS-XDATA	11 NC	
# 6 YC01	14 YD03	# 6* YSEL	# 4 CE-XY	12 NC	
# 7 YC01	15 YC11	# 7 GND	# 5 YSEL	13 NC	
# 8 GND	16 VCC	# 8* NC	# 6*CS-YDATA	14 VCC	

UNIVERSAL CONNECTOR FOR U.I.C. MEMORY CARD

PAGE 4

WIRE CONNECTIONS FOR U.I.C. MEMORY CARD

#E:23	#F:211	#F:216	#F:215	#F:214	#F:213	#F:212	#F:211	#F:210	#F:209	#F:208	#F:207	#F:206	#F:205	#F:204	#F:203	#F:202	#F:201	#F:200	#F:199	#F:198	#F:197	#F:196	#F:195	#F:194	#F:193	#F:192	#F:191	#F:190	#F:189	#F:188	#F:187	#F:186	#F:185	#F:184	#F:183	#F:182	#F:181	#F:180	#F:179	#F:178	#F:177	#F:176	#F:175	#F:174	#F:173	#F:172	#F:171	#F:170	#F:169	#F:168	#F:167	#F:166	#F:165	#F:164	#F:163	#F:162	#F:161	#F:160	#F:159	#F:158	#F:157	#F:156	#F:155	#F:154	#F:153	#F:152	#F:151	#F:150	#F:149	#F:148	#F:147	#F:146	#F:145	#F:144	#F:143	#F:142	#F:141	#F:140	#F:139	#F:138	#F:137	#F:136	#F:135	#F:134	#F:133	#F:132	#F:131	#F:130	#F:129	#F:128	#F:127	#F:126	#F:125	#F:124	#F:123	#F:122	#F:121	#F:120	#F:119	#F:118	#F:117	#F:116	#F:115	#F:114	#F:113	#F:112	#F:111	#F:110	#F:109	#F:108	#F:107	#F:106	#F:105	#F:104	#F:103	#F:102	#F:101	#F:100	#F:99	#F:98	#F:97	#F:96	#F:95	#F:94	#F:93	#F:92	#F:91	#F:90	#F:89	#F:88	#F:87	#F:86	#F:85	#F:84	#F:83	#F:82	#F:81	#F:80	#F:79	#F:78	#F:77	#F:76	#F:75	#F:74	#F:73	#F:72	#F:71	#F:70	#F:69	#F:68	#F:67	#F:66	#F:65	#F:64	#F:63	#F:62	#F:61	#F:60	#F:59	#F:58	#F:57	#F:56	#F:55	#F:54	#F:53	#F:52	#F:51	#F:50	#F:49	#F:48	#F:47	#F:46	#F:45	#F:44	#F:43	#F:42	#F:41	#F:40	#F:39	#F:38	#F:37	#F:36	#F:35	#F:34	#F:33	#F:32	#F:31	#F:30	#F:29	#F:28	#F:27	#F:26	#F:25	#F:24	#F:23	#F:22	#F:21	#F:20	#F:19	#F:18	#F:17	#F:16	#F:15	#F:14	#F:13	#F:12	#F:11	#F:10	#F:9	#F:8	#F:7	#F:6	#F:5	#F:4	#F:3	#F:2	#F:1	#F:0
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Port	Pin	Function									
1	C		5	XA1		9	XA1		9	YA1	
2	XA2		1C	XAC		10	XAD5		10	YDQ5	
3	XA7		11	XDGC		11	XDQ7		11	YDQ5	
4	XAC		12	XDQ1		12	XDQ1		12	YDQ7	
5	XA5		13	XDQ2		13	XDQ2		13	YDQ2	
6	XA4		14	GND		14	GND		14	GND	
7	XA3		15	XDQ3		15	XDQ3		15	YDQ3	
8	XA2		16	XDQ4		16	XDQ4		16	YDQ4	
9	XA1		17	XDQ5		17	XDQ5		17	YDQ5	
10	XAC		18	XAD6		18	XAD6		18	YDQ6	
11	XDGC		19	XDQ6		19	XDQ6		19	YDQ6	
12	XDQ1		20	CS-X4000		20	CS-X4000		20	CS-Y2000	
13	XDQ2		21	NXA10		21	NXA10		21	HYA10	
14	GND		22	XCE		22	XCE		22	YCE	
15	XDQ3		23	NXA11		23	NXA11		23	HYA11	
16	XDQ4		24	NXA9		24	NXA9		24	HYA9	
17	XDQ5		25	NXA0		25	NXA0		25	HYA0	
18	XAD6		26	NC		26	NC		26	NC	
19	XDQ6		27	XWE		27	XWE		27	YWE	
20	CS-X4000		28	VCC		28	VCC		28	VCC	
21	NXA10		22	XCE		22	XCE		22	XCE	
22	YCE		23	NXA11		23	NXA11		23	HYA11	
23	HYA11		24	HYA9		24	HYA9		24	HYA9	
24	HYA9		25	HYA0		25	HYA0		25	HYA0	

UNIT COMMISSIONING FORM UNIT MURRAY CARD

UNIT CONNECTIONS FOR UNID MEMORY CARD PAGE 7

NY-400
 # 1 AC 9 YA1 17 NYD05 25 NYA8
 # 2 YA12 10 YAC 18 NYD06 26 AC
 # 3 YA7 11 YD00 19 NYD07 27 YWF
 # 4 YA6 12 YD01 20 CS-Y4000 28 VCC
 # 5 YA5 13 YD02 21 NYA10
 # 6 YA4 14 G'D 22 YDF
 # 7 YA3 15 NYD03 23 NYA11
 # 8 YA2 16 YD04 24 NYA5

#Y-6035
1 YC
2 YA12
3 YA7
4 YA5
5 YA5
6 YA4
7 YA3
8 YA2
9 YA1
10 YAC
11 YD9C
12 YD01
13 YD32
14 GAC
15 YD3
16 YD04
17 NY005
18 NYD05
19 NYD07
20 CS-Y6000
21 NYA10
22 YCE
23 NYA11
24 NYA9

1	C	9	A1	17	S005	25	A9
2	A12	10	A1	18	S006	26	NC
3	A7	11	S005	19	S007	27	HR-SHARE
4	A6	12	S031	20	CR-S000	28	VCC
5	A5	13	S02	21	A1C		
6	A4	14	0	22	RD-SHARE		
7	A3	15	003	23	A11		
8	A2	16	004	24	A3		

UNIT CONNECTIONS FOR U.IO MEMORY CARD

#H:25

#S-AC01

# 1	*C	5	A1	17	SDQ5	25	AR
# 2	A12	10	AC	18	SDQ6	26	NC
# 3	A7	11	SDQ2	19	SDQ7	27	WR-SHARE
# 4	A6	12	SDQ1	20	CE-SA000	28	VCC
# 5	A5	13	SDQ2	21	A10		
# 6	A4	14	GxD	22	RD-SHARE		
# 7	A3	15	SDQ3	23	A11		
# 8	A2	16	SDQ4	24	A9		

#H:26

#S-CC01

# 1	IC	9	A1	17	SD05	25	AR
# 2	A12	10	AC	18	SD06	26	NC
# 3	A7	11	SD00	19	SDQ7	27	WR-SHARE
# 4	A6	12	SD01	20	CE-SC000	28	VCC
# 5	A5	13	SDQ2	21	A10		
# 6	A4	14	GxD	22	RD-SHARE		
# 7	A3	15	SD03	23	A11		
# 8	A2	16	SD04	24	A9		

#H:27

#S-EC01

# 1	AC	5	A1	17	SD05	25	AR
# 2	A12	10	AD	18	SD06	26	NC
# 3	A7	11	SD00	19	SDQ7	27	WR-SHARE
# 4	A6	12	SD01	20	CE-SE000	28	VCC
# 5	A5	13	SD02	21	A10		
# 6	A4	14	GxD	22	RD-SHARE		
# 7	A3	15	SD03	23	A11		
# 8	A2	16	SD04	24	A9		

PAGE 1

SIGNAL	FANOUT	SOURCE	SINKS			
A1	4	B:16/12	H:4/10	H:5/10	H:6/10	H:7/10
A1	4	B:16/9	H:4/9	H:5/9	H:6/9	H:7/9
A10	4	B:21/7	H:4/21	H:5/21	H:6/21	H:7/21
A11	4	B:21/4	H:4/23	H:5/23	H:6/23	H:7/23
A12	4	B:23/12	H:4/2	H:5/2	H:6/2	H:7/2
A13	1	B:23/9	D:23/1			
A14	1	B:23/7	D:23/2			
A15	1	B:23/4	D:23/3			
A2	4	B:16/7	H:4/2	H:5/8	H:6/8	H:7/8
A3	4	B:16/4	H:4/7	H:5/7	H:6/7	H:7/7
A4	4	B:16/12	H:4/6	H:5/6	H:6/6	H:7/6
A5	4	B:16/3	H:4/5	H:5/5	H:6/5	H:7/5
A6	4	B:16/7	H:4/4	H:5/4	H:6/4	H:7/4
A7	4	B:16/4	H:4/3	H:5/3	H:6/3	H:7/3

SIGNAL LIST FOR UNID MEMORY CARD
SIGNAL FANOUT SOURCE SINKS

PAGE 2

Ac	4	B:21/12	H:4/25	H:5/25	H:6/25	H:7/25
AS	4	B:21/9	H:4/24	H:5/24	H:6/24	H:7/24
CE-S8000	1	D:23/11	H:4/20			
CF-SA000	1	D:23/10	H:5/20			
CE-SC000	1	D:23/9	H:6/20			
CE-SE000	1	D:23/7	H:7/20			
CE-XY	2	F:22/6	E:17/24			
CF-XY200	3	D:23/14	E:12/1	F:12/1	F:22/5	
CE-XY400	3	D:23/13	E:12/4	F:12/4	F:22/4	
CF-XY600	3	D:23/12	E:12/9	F:12/9	F:22/3	
CS-SXDATA	2	F:22/8	B:11/1	C:12/1		
CS-SYDATA	2	F:11/8	B:13/1	C:14/1		
CS-X2000	1	F:12/3	G:1/20			
CS-X4000	1	F:12/6	G:2/20			
CS-X6000	1	F:12/8	G:3/20			

SIGNAL LIST FOR UNID MEMORY CARD

PAGE 3

SIGNAL	FANOUT	SOURCE	SINKS
CS-XDATA	2	E:17/3	E:23/1 F:23/1

CS-Y2000	1	E:12/3	H:1/20
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CS-Y4000	1	E:12/6	H:2/20
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CS-Y6000	1	E:12/8	H:3/20
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CS-YDATA	2	E:17/6	D:13/1 E:13/1
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G,D	57	A:1/120	B:11/8 B:13/8 B:16/8 B:18/8 B:21/8 B:23/8 C:12/8 C:14/8 C:17/7 D:13/8 D:16/7 D:18/7 D:21/7 D:23/4,5,8 E:11/7 E:12/7 E:13/8 E:15/7 E:17/7 E:19/7 E:23/8 F:11/7 F:12/7 F:13/7 F:14/1,8,15 F:15/1 F:15/8,15 F:16/1,8,15 F:17/7 F:18/1,8,15 F:19/1,8,15 F:21/1,8,15 F:22/7 F:23/8 G:1/14 G:2/14 G:3/14 H:1/14 H:2/14 H:3/14 H:4/14 H:5/14 H:6/14 H:7/14
-----	----	---------	-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------

LXA0	3	F:1/3	G:1/10 G:2/10 G:3/10
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LXA1	3	F:1/5	G:1/9 G:2/9 G:3/9
------	---	-------	-------------------

LXA10	3	F:1/11	G:1/21 G:2/21 G:3/21
-------	---	--------	----------------------

LXA11	3	F:1/13	G:1/23 G:2/23 G:3/23
-------	---	--------	----------------------

LXA12	3	F:16/3	G:1/2 G:2/2 G:3/2
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LXA131+15	1	O:1 /2	D:16/1
-----------	---	--------	--------

LXA2	3	F:1 /7	G:1/ G:2/ G:3/
------	---	--------	----------------

SIGNAL LIST FOR UNID MEMORY CARD					PAGE 4
SIGNAL	FAI/CUT SOURCE	SINKS			
UXA3	3 F:1~7	G:1/7 G:2/7 G:3/7			
UXA4	3 F:1 ~11	G:1/6 G:2/6 G:3/6			
UXA5	3 F:1 ~13	G:1/5 G:2/5 G:3/5			
UXA6	3 F:1 ~13	G:1/4 G:2/4 G:3/4			
UXA7	3 F:1 ~5	G:1/3 G:2/3 G:3/3			
UXA8	3 F:1 ~7	G:1/25 G:2/25 G:3/25			
UXA9	3 F:1 ~9	G:1/24 G:2/24 G:3/24			
UXDQC	4 F:23/2	F:23/4 G:1/11 G:2/11 G:3/11			
UXDQ1	4 F:23/5	F:23/7 G:1/12 G:2/12 G:3/12			
UXDQ2	4 F:23/9	F:23/11 G:1/13 G:2/13 G:3/13			
UXDQ3	4 F:23/12	F:23/14 G:1/15 G:2/15 G:3/15			
UXDQ4	4 E:23/2	E:23/4 G:1/16 G:2/16 G:3/16			
UXDQ5	4 E:23/5	E:23/7 G:1/17 G:2/17 G:3/17			
UXDQ6	4 E:23/9	E:23/11 G:1/18 G:2/18 G:3/18			
UXDQ7	4 E:23/12	E:23/14 G:1/19 G:2/19			

SIGNAL LIST FOR UNID MEMORY CARD
SIGNAL FAULT SOURCE SINKS
G:3/19

PAGE 5

NXPREQ	1	D:1/6	D:16/2
IXIE	1	E:1/2	F:22/2
IXFDSEL	1	D:1/12	D:16/13
IXSEL	2	E:15/6	E:17/1 F:22/10
LYAG	3	F:15/3	H:1/10 H:2/10 H:3/10
LYA1	3	F:15/5	H:1/9 H:2/9 H:3/9
LYA10	3	F:14/11	H:1/21 H:2/21 H:3/21
LYA11	3	F:14/13	H:1/23 H:2/23 H:3/23
LYA12	3	F:16/5	H:1/2 H:2/2 H:3/2
LYA131415	1	D:1/4	D:16/5
LYA2	3	F:15/7	H:1/5 H:2/5 H:3/8
LYA3	3	F:15/9	H:1/7 H:2/7 H:3/7
LYA4	3	F:15/11	H:1/6 H:2/6 H:3/6
LYA5	3	F:15/13	H:1/9 H:2/5 H:3/5
LYA6	3	F:14/5	H:1/4 H:2/4 H:3/4
LYA7	3	F:14/5	H:1/3 H:2/3 H:3/3

SIGNAL LIST FOR QLID MEMORY CARD
 SIGNAL FANTUT SOURCE SINKS

PAGE 6

NYA4 3 F:14/7 H:1/25 H:2/25 H:3/25

NYA9 3 F:14/9 H:1/24 H:2/24 H:3/24

NYDQ0 4 E:13/2 E:13/4 H:1/11 H:2/11 H:3/11

NYDQ1 4 E:13/5 E:13/7 H:1/12 H:2/12 H:3/12

NYDQ2 4 E:13/9 E:13/11 H:1/13 H:2/13
H:3/13

NYDQ3 4 E:13/12 E:13/14 H:1/15 H:2/15
H:3/15

NYDQ4 4 D:13/2 D:13/4 H:1/16 H:2/16 H:3/16

NYDQ5 4 D:13/5 D:13/7 H:1/17 H:2/17 H:3/17

NYDQ6 4 D:13/9 D:13/11 H:1/18 H:2/18
H:3/18

NYDQ7 4 D:13/12 D:13/14 H:1/19 H:2/19
H:3/19

NYDFE0 1 D:14/5 D:16/4

NYDFE 1 E:14/6 F:11/2

NYDSE0 1 D:14/10 D:16/9

NYDL 2 E:14/12 E:17/5 F:11/10

SIGNAL LIST FOR VOID MEMORY CARD
 SIGNAL FA' CUT SOURCE SINK
 RD-SHA E 4 F:17/3 H:4/22 H:5/22 H:6/22 H:7/22 PAGE 7

SD00	7	C:12/2	C:12/4	C:14/2,4	H:4/11	H:5/11	H:6/11	H:7/11
SD01	7	C:12/5	C:12/7	C:14/5,7	H:4/12	H:5/12	H:6/12	H:7/12
SD02	7	C:12/9	C:12/11	C:14/9,11	H:4/13	H:5/13	H:6/13	H:7/13
SD03	7	C:12/12	C:12/14	C:14/12,14	H:4/15	H:5/15	H:6/15	H:7/15
SD04	7	B:11/2	B:11/4	B:13/2,4	H:4/16	H:5/16	H:6/16	H:7/16
SD05	7	B:11/5	B:11/7	B:13/5,7	H:4/17	H:5/17	H:6/17	H:7/17
SD06	7	B:11/7	B:11/11	B:13/9,11	H:4/18	H:5/18	H:6/18	H:7/18
SD07	7	B:11/12	B:11/14	B:13/12,14	H:4/19	H:5/19	H:6/19	H:7/19
SD-BE	4	F:17/3	B:11/15	B:13/15	B:21/15	B:23/15		
VOC	4 ^a	A:1/6	B:11/16	B:13/16	B:16/16	B:17/16	B:21/16	B:23/16
			C:12/16	C:14/16	C:17/16			
			D:13/16	D:16/14	D:1e/14			
			D:21/14	D:23/6,14	D:11/14			
			E:12/14	E:13/14	E:15/14			
			E:17/14	E:19/14	E:23/16			
			F:11/1,11,14	F:12/14	F:13/14			
			F:14/16	F:15/16	F:16/16			
			F:17/14	F:18/16	F:19/16			

SIGNAL LIST FOR UNID MEMORY CARD				PAGE	8
SIGNAL	FANOUT SOURCE	SINKS			
		F:21/16	F:22/1,11,14	F:23/16	
		G:1/28	G:2/28	G:3/28	H:1/28
		H:2/28	H:3/28	H:4/28	H:5/28
		H:6/28	H:7/28		
WR-SHATE	4	F:17/6	H:4/27	H:5/27	H:6/27
X1	1	F:21/11	F:22/9		
XA	2	A:1/90	B:16/13	F:16/2	
XA1	2	A:1/92	B:16/10	F:19/4	
XA10	2	A:1/33	B:21/6	F:18/12	
XA11	2	A:1/35	B:21/3	F:18/14	
XA12	2	A:1/30	B:23/13	F:16/2	
XA13	2	A:1/32	B:23/10	D:21/13	
XA131415	1	D:21/12	D:15/1		
XA14	2	A:1/34	B:23/6	D:21/2	
XA15	3	A:1/36	B:23/3	D:21/1	F:21/12
XA	2	A:1/34	B:16/6	F:15/6	
XA'	2	A:1/46	B:16/3	F:15/10	
XA6	2	A:1/91	B:15/13	F:15/12	

SIGNAL LIST FOR U11D MEMORY CARD				PAGE	6
SIGNAL	FANOUT	SOURCE	SINK		
XA	2	A:1/93	B:18/10	F:19/14	
XA4	2	A:1/95	B:18/6	F:18/2	
XA7	2	A:1/57	B:18/3	F:16/4	
XA8	2	A:1/29	B:21/13	F:15/6	
XA9	2	A:1/31	B:21/10	F:18/10	
XA BIT	2	D:16/3	E:15/2	F:13/9	
XCLK/3	1	A:1/56	C:17/5		
XD18	2	F:23/12	E:23/15	F:23/15	
XD00	2	A:1/60	C:12/3	F:23/3	
XD01	2	A:1/62	C:12/6	F:23/6	
XD02	2	A:1/7	C:12/10	F:23/10	
XD03	2	A:1/5	C:12/13	F:23/13	
XD04	2	A:1/70	B:11/3	E:23/3	
XD05	2	A:1/71	B:11/6	F:23/6	
XD06	2	A:1/5	B:11/10	F:23/10	
XD07	2	A:1/10	B:11/15	F:23/13	
XD08	1	A:1/11	D:11/5		

SIGNAL LIST FOR VOID MEMORY CARD
 SIGNAL FAUCET SOURCE SINKS
 X:E 4 F:21/9 E:19/1 G:1/22 G:2/22 G:3/22

PAGE 13

XRD	2	A:1/111	E:11/5	F:21/10	
XFDSL	2	E:11/6	D:15/13	F:17/10	
XDDE	2	D:16/11	B:11/15	C:12/15	
XDFL	9	E:15/3	E:11/1,4	E:15/4	E:19/5
			F:12/2,5,10	F:15/2	F:17/1
XWAIT	1	F:13/8	A:1/55		
XW	4	F:21/5	F:22/13	G:1/27	G:2/27
				H:3/27	
XW	2	A:1/117	F:11/2	F:21/4	
XXSEL	2	E:11/3	D:16/12	F:17/4	
XYARCH	2	F:13/8	F:13/1,5		
Y1	1	F:21/13	F:11/9		
YA	2	A:1/100	B:16/14	F:15/2	
YAI	2	A:1/102	B:16/11	F:15/4	
YAL	2	A:1/43	B:21/5	F:14/12	
YAI1	2	A:1/45	B:21/2	C:14/14	
YAI2	2	A:1/46	B:23/14	F:15/4	

SIGNAL LIST FOR U.I.D MEMORY CARD
SIGNAL FAULT SOURCE SINKS
YA13 2 A:1/42 B:23/11 D:21/9

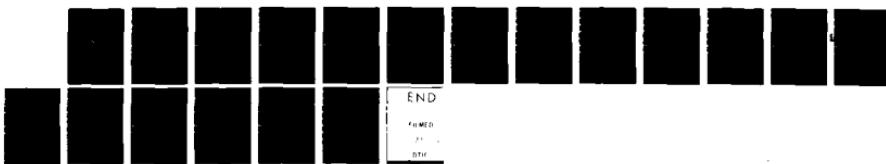
PAGE 11

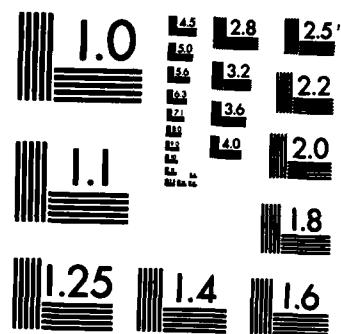
YA131415 1 D:21/8 B:18/3
YA14 2 A:1/44 B:23/5 D:21/10
YA15 3 A:1/46 B:23/2 D:21/11 F:21/14
YA1 2 A:1/104 B:16/5 F:15/6
YA2 2 A:1/106 B:16/2 F:15/10
YA3 2 A:1/101 B:18/14 F:15/12
YA4 2 A:1/103 B:18/11 F:15/14
YA5 2 A:1/105 B:18/5 F:14/2
YA6 2 A:1/107 B:18/2 F:14/4
YA7 2 A:1/34 B:21/14 F:14/6
YA8 2 A:1/41 B:21/11 F:14/10
YA-BIT 2 D:16/6 E:15/F F:13/10
YCLK/Z 1 C:17/5 A:17/6
YD_EI 2 F:11/12 D:13/15 F:13/15
YD_EI 2 A:1/74 C:14/3 F:13/3
YD_O1 2 A:1/75 C:14/4 F:13/6

AD-A126 031

CONTINUED DEVELOPMENT OF THE UNIVERSAL NETWORK
INTERFACE DEVICE(U) AIR FORCE INST OF TECH
WRIGHT-PATTERSON AFB OH SCHOOL OF ENGINEERING G CUOMO
UNCLASSIFIED DEC 82 AFIT/GE/EE/82D-28 F/G 9/2 NL

2/2





MICROCOPY RESOLUTION TEST CHART
NATIONAL BUREAU OF STANDARDS-1963-A

SIGNAL LIST FOR UNID MEMORY CARD

	SIGNAL	FANOUT SOURCE	SINKS
	YD02	2 A:1/13	C:14/10 E:13/10
	YD03	2 A:1/14	C:14/13 E:13/13
	YD04	2 A:1/76	B:13/3 D:13/3
	YD05	2 A:1/77	B:13/6 D:13/6
	YD06	2 A:1/15	B:13/10 D:13/10
	YD07	2 A:1/16	B:13/13 D:13/13
	YM-EQ	1 A:1/112	D:18/9
	YCF	4 F:21/7	E:19/9 H:1/22 H:2/22 H:3/22
	YRD	2 A:1/113	E:11/13 F:21/6
	YDSEL	2 E:11/11	D:18/11 F:17/9
	YDSEL	2 D:16/8	B:13/15 C:14/15
	YSEL	13 E:16/6	B:16/1 B:17/1 H:21/1 R:23/1 E:11/10,12 E:12/2,5,10 E:15/1 E:19/13 F:13/4 F:17/2
	YWAIT	1 F:13/3	A:1/57
	YWF	4 F:21/3	F:11/13 H:1/27 H:2/27 H:3/27
	YW	2 A:1/119	E:11/9 F:21/2

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SIGNAL LIST FOR U110 MEMORY CARD
SIGNAL FANOUT SOURCE SINKS
YW-SFL 2 E:11/9 D:16/10 F:17/5

PAGE 13

LIFE LIST FOR UNID MEMORY CARD
LEVEL 1

PAGE 1

A:1/30	B:23/3	XA15
A:1/46	B:23/2	YA15
A:1/55	F:13/6	XWAIT
A:1/56	C:17/5	XCLK/2
A:1/57	F:13/3	YWAIT
A:1/58	C:17/6	YCLK/2
A:1/110	D:18/5	XREQ
A:1/112	D:18/0	YREQ

B:11/1	C:12/1	CS-SXDATA
B:11/2	B:11/4	SDQ4
B:11/3	E:23/3	XDQ4
B:11/5	B:11/7	SDQ5
B:11/6	E:23/6	XDQ5
B:11/7	B:11/11	SDQ6
B:11/10	E:23/10	XDQ6
B:11/12	H:11/14	SDQ7
B:11/13	E:23/13	XDQ7
B:11/15	C:12/15	XSDIEN

B:13/1	C:14/1	CS-SYDATA
B:13/2	B:13/4	SDQ4
B:13/3	D:13/3	YDQ4
B:13/5	B:13/7	SDQ5
B:13/6	D:13/6	YDQ5
B:13/7	B:13/11	SDQ6
B:13/10	D:13/10	YDQ6
B:13/12	B:13/14	SDQ7
B:13/13	D:13/13	YDQ7
B:13/15	C:14/15	YSDIEN

B:16/1	B:15/1	YSFL
B:16/2	F:15/10	YA3
B:16/3	F:15/10	XA3
B:16/5	F:15/5	YA2
B:16/6	F:15/6	XA2
B:16/10	F:15/4	XA1
B:16/11	F:15/4	YA1
B:16/13	F:15/2	XA0
B:16/14	F:15/2	YA0
B:16/15	H:15/15	STPCHE

B:17/2	F:14/4	YA7
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WIRE LIST FOR UNID MEMORY CARD
LEVEL 1

PAGE 2

B:18/3	F:18/4	XA7
B:18/5	F:14/2	YA6
B:18/6	F:18/2	XAG
B:18/10	F:15/14	XA5
B:18/11	F:15/14	YA5
B:18/13	F:15/12	XA4
B:18/14	F:15/12	YA4

B:21/1	B:23/1	YSEL
B:21/2	F:14/14	YA11
B:21/3	F:18/14	XA11
B:21/5	F:14/12	YA10
B:21/5	F:18/12	XA10
B:21/10	F:18/10	XA9
B:21/11	F:14/10	YA9
B:21/13	F:18/6	XA8
B:21/14	F:14/6	YA8
B:21/15	B:23/15	STROBE

B:23/4	D:23/3	A15
B:23/5	D:21/14	YA14
B:23/6	D:21/2	XA14
B:23/7	D:23/2	A14
B:23/9	D:23/1	A13
B:23/10	D:21/13	XA13
B:23/11	D:21/1	YA13
B:23/13	F:16/2	XA12
B:23/14	F:16/4	YA12

C:12/2	C:12/4	SDQ0
C:12/3	F:23/3	XJQ0
C:12/5	C:12/7	SDQ1
C:12/6	F:23/5	XDQ1
C:12/7	C:12/11	SDQ2
C:12/10	F:23/10	XDQ2
C:12/12	C:12/14	SDQ3
C:12/13	F:23/13	XDQ3

C:14/2	C:14/4	SDQ0
C:14/3	E:13/3	YDQ0
C:14/5	C:14/7	SDQ1
C:14/6	E:13/6	YDQ1
C:14/7	C:14/11	SDQ2
C:14/17	E:13/10	YDQ2

WIRE LIST FOR UNID MEMORY CARD
LEVEL 1

PAGE 3

C:14/12	C:14/14	SDQ3
C:14/13	E:13/15	YDQ3

D:13/1	E:13/1	CS-YDATA
D:13/4	H:1/16	NYDQ4
D:13/7	H:1/17	NYDQ5
D:13/11	H:1/18	NYDQ6
D:13/14	H:1/19	NYDQ7
D:13/15	E:13/15	YDIEN

D:16/1	D:18/2	NXA131415
D:16/2	D:18/6	NXMREQ
D:16/4	D:18/8	NYMREQ
D:16/5	D:18/4	NYA131415
D:16/7	D:18/10	NYRDSEL
D:16/10	F:17/5	YWRSEL
D:16/12	F:17/4	XWPSEL
D:16/13	D:18/12	NXRDSEL

D:18/1	D:21/12	XA131415
D:18/5	D:21/8	YA131415
D:18/11	F:17/9	YRDSEL
D:18/13	F:17/10	XRDSEL

D:21/1	F:21/12	XA15
D:21/11	F:21/14	YA15

D:23/7	H:7/20	CE-SE000
D:23/9	H:6/20	CE-SC000
D:23/10	H:5/20	CE-SA000
D:23/11	H:4/20	CE-SB000
D:23/12	F:22/3	CE-XY6000
D:23/13	F:22/4	CE-XY4000
D:23/14	F:22/5	CE-XY2000

E:11/1	E:11/4	XSEL
E:11/2	F:21/4	XWR
E:11/5	F:21/10	XRD
F:11/1	F:21/2	YN
F:11/11	F:12/1	YSEL
F:11/12	F:13/4	YSEL
F:11/13	F:21/6	YRD

WIPE LIST FOR UNID MEMORY CARD
LEVEL 1

PAGE 4

E:12/1	F:12/1	CE-XY2000
E:12/2	E:12/5	YSEL
E:12/3	H:1/20	CS-Y2000
E:12/4	F:12/4	CE-XY4000
E:12/5	H:2/20	CS-Y4000
E:12/6	H:3/20	CS-Y6000
E:12/7	F:12/7	CE-XY6000

E:13/4	H:1/11	NYDQ0
F:13/7	H:1/12	NYDQ1
E:13/11	H:1/13	NYDQ2
E:13/14	H:1/15	NYDQ3

E:15/1	E:15/6	YSEL
E:15/2	F:13/9	XARBIT
E:15/3	E:15/4	XSEL
E:15/5	F:13/10	YARBIT

E:17/1	E:19/6	NXSEL
F:17/2	E:17/4	CE-XY
F:17/5	F:11/10	NYSEL

E:19/1	F:21/9	XCE
E:19/2	F:22/2	NYOE
F:19/5	F:17/1	XSEL
F:19/6	F:11/2	NYOE
E:19/7	F:21/1	YCE
E:19/13	F:17/2	YSEL

F:23/1	F:23/1	CS-XDATA
E:23/4	G:1/16	NXDQ4
E:23/7	G:1/17	NXDQ5
E:23/11	G:1/18	NXDQ6
F:23/14	G:1/19	NXDQ7
E:23/15	F:23/15	XDIEN

F:11/8	F:21/13	Y15
F:11/15	F:21/5	YWE

F:12/2	F:13/2	XSEL
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WIFE LIST FOR UNID MEMORY CARD
LEVEL 1

PAGE . 5

F:12/3	G:1/20	CS-X2000
F:12/5	E:15/3	XSEL
F:12/6	G:2/20	CS-X4000
F:12/4	G:3/20	CS-X6000

F:13/1 F:13/5 XYARHIT

F:14/3	H:1/4	NYA6
F:14/5	H:1/3	NYA7
F:14/7	H:1/25	NYA8
F:14/9	H:1/24	NYA9
F:14/11	H:1/21	NYA10
F:14/13	H:1/23	NYA11

F:15/3	H:1/10	NYA0
F:15/5	H:1/9	NYA1
F:15/7	H:1/8	NYA2
F:15/9	H:1/7	NYA3
F:15/11	H:1/6	NYA4
F:15/13	H:1/5	NYA5

F:16/3 G:1/2 NXA12
F:16/5 H:1/2 NYA12

F:16/3	G:1/4	NXA6
F:16/5	G:1/3	NXA7
F:16/7	G:1/25	NXA8
F:16/9	G:1/24	NXA9
F:16/11	G:1/21	NXA10
F:16/13	G:1/23	NXA11

F:19/3	G:1/10	NXA0
F:19/5	G:1/5	NXA1
F:19/7	G:1/8	NXA2
F:19/9	G:1/7	NXA3
F:19/11	G:1/6	NXA4
F:19/13	G:1/5	NXA5

F:21/11 F:22/9 X15

F:22/11 G:1/27 XWE

WIFE LIST FOR UNID MEMORY CARD
LEVEL 1

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F:23/4	G:1/11	NXDQ3
F:23/7	G:1/12	NXDQ1
F:23/11	G:1/13	NXDQ2
F:23/14	G:1/15	NXDQ3

G:1/22	G:2/22	XOE
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G:2/2	G:3/2	NXA12
G:2/3	G:3/3	NXA7
G:2/4	G:3/4	NXA6
G:2/5	G:3/5	NXA5
G:2/6	G:3/6	NXA4
G:2/7	G:3/7	NXA3
G:2/8	G:3/8	NXA2
G:2/9	G:3/9	NXA1
G:2/10	G:3/10	NXA0
G:2/11	G:3/11	NXDQ3
G:2/12	G:3/12	NXDQ1
G:2/13	G:3/13	NXDQ2
G:2/15	G:3/15	NXDQ3
G:2/16	G:3/16	NXDQ4
G:2/17	G:3/17	NXDQ5
G:2/18	G:3/18	NXDQ6
G:2/19	G:3/19	NXDQ7
G:2/21	G:3/21	NXA13
G:2/23	G:3/23	NXA11
G:2/24	G:3/24	NXA9
G:2/25	G:3/25	NXA3
G:2/27	G:3/27	XWE

H:1/22	H:2/22	YF
H:1/27	H:2/21	YWE

H:2/2	H:3/2	NYA12
H:2/3	H:3/3	NYA7
H:2/4	H:3/4	NYA6
H:2/5	H:3/5	NYA5
H:2/6	H:3/6	NYA4
H:2/7	H:3/7	NYA3
H:2/8	H:3/8	NYA2
H:2/9	H:3/9	NYA1
H:2/10	H:3/10	NYAC

WIRE LIST FOR UNID MEMORY CARD
LEVEL 1

PAGE 7

H:2/11	H:3/11	NYDQC
H:2/12	H:3/12	NYQ01
H:2/13	H:3/13	NYDQ2
H:2/15	H:3/15	NYDQ3
H:2/16	H:3/16	NYDQ4
H:2/17	H:3/17	NYDQ5
H:2/18	H:3/18	NYDQ6
H:2/19	H:3/19	NYDQ7
H:2/21	H:3/21	NYA10
H:2/23	H:3/23	NYA11
H:2/24	H:3/24	NYA9
H:2/25	H:3/25	NYA8

H:4/2	H:5/2	A12
H:4/3	H:5/3	A7
H:4/4	H:5/4	A6
H:4/5	H:5/5	A5
H:4/6	H:5/6	A4
H:4/7	H:5/7	A3
H:4/8	H:5/8	A2
H:4/9	H:5/9	A1
H:4/10	H:5/10	A6
H:4/11	H:5/11	SDQ0
H:4/12	H:5/12	SDQ1
H:4/13	H:5/13	SDQ2
H:4/15	H:5/15	SDQ3
H:4/16	H:5/16	SDQ4
H:4/17	H:5/17	SDQ5
H:4/18	H:5/18	SDQ6
H:4/19	H:5/19	SDQ7
H:4/21	H:5/21	A1C
H:4/22	H:5/22	RD-SHARE
H:4/23	H:5/23	A11
H:4/24	H:5/24	A9
H:4/25	H:5/25	A8
H:4/27	H:5/27	WR-SHARE

H:6/2	H:7/2	A12
H:6/3	H:7/3	A7
H:6/4	H:7/4	A6
H:6/5	H:7/5	A5
H:6/6	H:7/6	A4
H:6/7	H:7/7	A3
H:6/8	H:7/8	A2
H:6/9	H:7/9	A1
H:6/10	H:7/10	A0

WIRE LIST FOR UNID MEMORY CARD
LEVEL 1

PAGE 3

H:6/11	H:7/11	SDQ0
H:6/12	H:7/12	SDQ1
H:6/13	H:7/13	SDQ2
H:6/15	H:7/15	SDQ3
H:6/16	H:7/16	SDQ4
H:6/17	H:7/17	SDQ5
H:6/18	H:7/18	SDQ6
H:6/19	H:7/19	SDQ7
H:6/21	H:7/21	A10
H:6/22	H:7/22	RD-SHAPE
H:6/23	H:7/23	A11
H:6/24	H:7/24	A9
H:6/25	H:7/25	A8
H:6/27	H:7/27	WR-SHAPE

WIRE LIST FOR UNID MEMORY CARD
LEVEL 2

PAGE 9

A:1/7	F:23/10	XDQ2
A:1/8	F:23/13	XDQ3
A:1/9	E:23/10	XDQ6
A:1/10	E:23/13	XDQ7
A:1/13	C:14/10	YDQ2
A:1/14	C:14/13	YDQ3
A:1/15	B:13/10	YDQ5
A:1/16	B:13/13	YDQ7
A:1/29	B:21/13	XA8
A:1/30	B:23/13	XA12
A:1/31	B:21/10	XA9
A:1/32	B:23/10	XA13
A:1/33	B:21/6	XA10
A:1/34	B:23/6	XA14
A:1/35	B:21/3	XA11
A:1/39	B:21/14	YA..
A:1/40	B:23/14	YA12
A:1/41	B:21/11	YA9
A:1/42	B:23/11	YA13
A:1/43	B:21/5	YA10
A:1/44	B:23/5	YA14
A:1/45	B:21/2	YA11
A:1/67	F:23/3	XDQC
A:1/68	F:23/6	-XDQ1
A:1/70	E:23/3	XDQ4
A:1/71	E:23/6	XDQ5
A:1/74	C:14/3	YDQC
A:1/75	C:14/6	YDQ1
A:1/76	B:13/3	YDQ4
A:1/77	B:13/6	YDQ5
A:1/80	B:16/13	XA6
A:1/81	B:18/13	XA4
A:1/82	B:16/10	XA1
A:1/83	B:18/10	XA5
A:1/84	B:16/6	XA2
A:1/85	B:18/6	XA6
A:1/86	B:16/5	XA3
A:1/87	B:18/5	XA7
A:1/100	B:16/14	YA6
A:1/101	B:18/14	YA4
A:1/102	B:16/11	YA1
A:1/103	B:18/11	YA5
A:1/104	B:16/5	YA6
A:1/105	B:18/5	YA1
A:1/106	B:16/2	YA3
A:1/107	B:18/2	YA7

WIRE LIST FOR UNID MEMORY CARD
LEVEL 2

PAGE 10

A:1/111	F:21/10	XRD
A:1/113	F:21/6	YRD
A:1/117	F:21/4	XWR
A:1/119	F:21/2	YWR

B:11/4	B:13/2	SDQ4
B:11/7	B:13/5	SDQ5
B:11/11	B:13/9	SDQ6
B:11/14	B:13/12	SDQ7

B:13/1	F:11/8	CS-SYDATA
B:13/4	H:4/16	SDQ4
B:13/7	H:4/17	SDQ5
B:13/11	H:4/18	SDQ6
B:13/14	H:4/19	SDQ7

B:16/1	B:21/1	YSEL
B:16/4	H:4/7	A3
B:16/7	H:4/6	A2
B:16/9	H:4/9	A1
B:16/12	H:4/10	A0
B:16/15	F:17/3	STROBE

B:18/1	E:19/13	YSEL
B:18/4	H:4/3	A7
B:18/7	H:4/4	A6
B:18/9	H:4/5	A5
B:18/12	H:4/6	A4
B:16/15	H:21/15	STROBE

B:21/4	H:4/23	A11
B:21/7	H:4/21	A10
B:21/10	H:4/24	A9
B:21/12	H:4/25	A8

B:23/2	D:21/11	YA15
B:23/3	D:21/1	XA15
B:23/12	H:4/2	A12

C:12/1	F:22/6	CS-SXDATA
C:12/4	C:14/2	SDQ0

WIRE LIST FOR UNID MEMORY CARD
LEVEL 2

PAGE .11

C:12/7	C:14/5	SDQ1
C:12/11	C:14/9	SDQ2
C:12/14	C:14/12	SDQ3
C:12/15	D:16/11	XSDIEN

C:14/4	H:4/11	SDQ0
C:14/7	H:4/12	SDQ1
C:14/11	H:4/13	SDQ2
C:14/14	H:4/15	SDQ3
C:14/15	D:16/12	YSDIEN

D:13/2	D:13/4	NYDQ4
D:13/5	D:13/7	NYDQ5
D:13/9	D:13/11	NYDQ6
D:13/12	D:13/14	NYDQ7

D:16/3	E:15/2	XARBIT
D:16/5	E:15/5	YARBIT
D:16/10	E:11/9	YWRSEL
D:16/12	E:11/3	XWRSEL

E:11/1	F:12/10	XSEL
E:11/6	F:17/10	XRDSEL
E:11/10	E:11/12	YSEL
E:11/11	F:17/9	YFDSEL

E:12/2	E:15/1	YSEL
E:12/5	E:12/10	YSEL

E:13/1	E:17/0	CS-YDATA
E:13/2	E:13/4	NYDQ0
E:13/5	E:13/11	NYDQ1
E:13/7	E:13/11	NYDQ2
E:13/12	E:13/14	NYDQ3
E:13/15	F:11/12	YDIEN

E:15/3	F:17/1	XSEL
E:15/4	F:12/2	XSEL
E:15/6	F:17/2	YSEL
E:15/4	F:12/5	XSEL

E:17/2	F:22/0	CE-KY
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WHITE LIST FOR UNID MEMORY CARD
LEVEL 2

PAGE . 12

E:17/3 E:23/1 CS-XDATA
E:17/5 E:19/12 NYSEL

E:19/6 F:22/10 NYSEL

E:23/2 E:23/4 NXDQ4
F:23/5 E:23/7 NXDQ5
F:23/9 E:23/11 NXDQ6
E:23/12 E:23/14 NXDQ7

F:12/1 D:23/14 CE-KY2000

F:12/4 D:23/13 CE-KY4000
F:12/9 D:23/12 CE-KY6000

F:13/1 F:13/2 XYARHIT

F:17/8 H:4/27 WR-SHARE
F:17/9 H:4/22 PD-SHARE

F:21/3 H:1/21 YWE
F:21/5 F:22/13 XWE
F:21/7 H:1/22 YOE
F:21/9 G:1/22 XOE

F:22/12 F:23/16 XDIER

F:23/2 F:23/4 NXDQ0
F:23/5 F:23/7 NXDQ1
F:23/8 F:23/11 NXDQ2
F:23/12 F:23/14 NXDQ3

G:1/2 G:2/2 NXA12
G:1/3 G:2/3 NXA7
G:1/4 G:2/4 NYAG
G:1/5 G:2/5 LXAS
G:1/6 G:2/6 LXAA
G:1/7 G:2/7 NYA3
G:1/8 G:2/8 NXA2

WIRE LIST FOR UNID MEMORY CARD
LEVEL 2

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G:1/5	G:2/9	NXA1
G:1/10	G:2/10	NXA0
G:1/11	G:2/11	NXDQ0
G:1/12	G:2/12	NXDQ1
G:1/13	G:2/13	NXDQ2
G:1/15	G:2/15	NXDQ3
G:1/16	G:2/16	NXDQ4
G:1/17	G:2/17	NXDQ5
G:1/18	G:2/18	NXDQ6
G:1/19	G:2/19	NXDQ7
G:1/21	G:2/21	NXA1C
G:1/23	G:2/23	NXA11
G:1/24	G:2/24	NXA9
G:1/25	G:2/25	NXAE
G:1/27	G:2/27	XWE

G:2/22 G:3/22 XSE

H:1/2	H:2/2	NYA12
H:1/3	H:2/3	NYA7
H:1/4	H:2/4	NYA6
H:1/5	H:2/5	NYA5
H:1/6	H:2/6	NYA4
H:1/7	H:2/7	NYA3
H:1/8	H:2/8	NYA2
H:1/9	H:2/9	NYA1
H:1/10	H:2/10	NYA0
H:1/11	H:2/11	NYDQ0
H:1/12	H:2/12	NYDQ1
H:1/13	H:2/13	NYDQ2
H:1/15	H:2/15	NYDQ3
H:1/16	H:2/16	NYDQ4
H:1/17	H:2/17	NYDQ5
H:1/18	H:2/18	NYDQ6
H:1/19	H:2/19	NYDQ7
H:1/21	H:2/21	NYA1C
H:1/23	H:2/23	NYA11
H:1/24	H:2/24	NYA9
H:1/25	H:2/25	NYAc

H:2/22 H:3/22 YSE
H:1/27 H:5/27 YWE

H:1/2 H:3/2 A12

WIRE LIST FOR UNID MEMORY CARD
LEVEL 2

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H:5/3	H:6/3	A7
H:5/4	H:6/4	A6
H:5/5	H:6/5	A5
H:5/6	H:6/6	A4
H:5/7	H:6/7	A3
H:5/8	H:6/8	A2
H:5/9	H:6/9	A1
H:5/10	H:6/10	A.
H:5/11	H:6/11	SDQJ
H:5/12	H:6/12	SDQ1
H:5/13	H:6/13	SDQ2
H:5/15	H:6/15	SDQ3
H:5/16	H:6/16	SDQ4
H:5/17	H:6/17	SDQ5
H:5/18	H:6/18	SDQ6
H:5/19	H:6/19	SDQ7
H:5/21	H:6/21	A10
H:5/22	H:6/22	RD-SHARE
H:5/23	H:6/23	A11
H:5/24	H:6/24	A9
H:5/25	H:6/25	A8
H:5/27	H:6/27	WR-SHARE
D:23/12	F:12/9	CE-XY6000
D:23/13	F:12/4	CE-XY4000
D:23/14	F:12/1	CE-XY2000

Vita

Gennaro Cuomo was born on 28 August 1947 in New York City, New York. He graduated from Plainview High School, New York in 1965 after which he attended Nassau Community College, Garden City, New York. In May 1967, he entered the U.S. Air Force. In July 1968, he entered the United States Air Force Academy Preparatory School and was graduated from the USAF Academy in June 1973 with a Bachelor of Science degree in Electrical Engineering. Following graduation, he attended Undergraduate Navigator Training (UNT) at Mather AFB, California. Upon graduation from UNT, he entered Electronic Warfare Training (EWT) also at Mather AFB. After EWT, he was trained as an Electronic Warfare Officer (EWO) aboard a B-52H at Castle AFB, California. He was then assigned to Kincheloe AFB, Michigan from March 1975 through June 1977. Upon the closure of Kincheloe AFB, he was assigned to Ellsworth AFB, South Dakota as an Instructor EWO, from July 1977 through November 1980. He entered the Air Force Institute of Technology in December 1980.

Permanent Address: 3 Forest Drive

Plainview, New York 11803

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20. ABSTRACT (Continue on reverse side if necessary and identify by block number) The object of this investigation was to design and construct two memory boards for the Digital Engineering Laboratory Network's (DELNET's) Universal Network Interface Devices (UNIDs). The UNID is a flexible message processor designed for computer communications network applications. The new memory boards incorporated the prototype microcomputer based message processor boards of the previous theses. Using the existing memory boards, new memory boards were designed, constructed, tested, and documented. The results of this effort were the elimination of unreliable RAM, the reduction in the number of circuit boards used in the UNID, and two operational UNIDs.		